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(54) **CONNECTOR AND METALLIC MATERIAL FOR CONNECTOR**
VERBINDER UND METALLMATERIAL FÜR EINEN VERBINDER
CONNECTEUR ET MATERIAU METALLIQUE POUR CONNECTEUR

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(56) References cited:
EP-A1- 1 026 287 **JP-A- 2003 213 486**
JP-A- 2004 179 055 **JP-A- 2004 339 555**
JP-A- 2004 339 555 **JP-A- 2006 114 492**
JP-A- 2006 114 492 **JP-A- 2006 324 063**
US-A1- 2003 091 855 **US-A1- 2003 186 597**

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Description

Technical field

5 **[0001]** The present invention relates to a metallic material for a connector and its production method.

Background art

10 **[0002]** In general there are made use of a male terminal and a female terminal for such as a connector to be made use for a connection to between an electric wire in a motor vehicle or the like, in which there are provided a metal covering layer of such as a tin (Sn) or an alloy of tin or the like on an electrically conductive substrate (refer to as a substrate properly hereinafter) of such as an alloy of copper (Cu) or the like. Moreover, such the male terminal and the female terminal are individually housed in a housing, and then each of such the terminals is configured as a male connector and a female connector respectively. Further, there is known a metallic material as a high performance electric conductor that has a substrate which is superior in the electrical conductivity and a strength thereof, that has a metal covering layer which is superior in an electrical connectability and a corrosion resistance and in a solderability thereon, that is to be made use for a material of the male terminal and for a material of the female terminal, in which there is provided the metal covering layer of such as Sn or the alloy of Sn or the like on the electrically conductive substrate of such as Cu or the alloy of Cu or the like by making use of such as a plating or the like (refer to the following Patent Document 1 to 20 4 for example). Still further, regarding such the metallic material in general, there is designed to be formed an underlayer of nickel (Ni) or cobalt (Co) or of iron (Fe) or the like by making use of such as the plating or the like, that individually have a barrier function in order to prevent an alloy content of such as zinc (Zn) or the like in the substrate (refer to as a substrate element properly hereinafter) from diffusing into the above mentioned metal covering layer.

25 **[0003]** Still further, there becomes to be formed an oxide film layer on a surface of such the metal covering layer of such as Sn or the like on a surface of the terminal due to the Sn thereon as easier to be oxidized under an environment at a temperature as higher, such as at an inside of an engine room of the motor vehicle or the like. And then due to such the oxide film layer as short, it is able to obtain an electrical connectability of therebetween as excellently because such the oxide film layer becomes to be torn thereby at a time of a connection of the terminal thereto, and then because there becomes to be exposed unoxxygenated Sn from an inside of an under layered metal covering layer.

30 **[0004]** In recent years on the contrary thereto, there becomes such the connector to be as a multi way type in a period of progressing an electronic control thereof, and then it becomes to be required a force as further larger at a time of inserting therein or extracting therefrom a group of terminals that are comprised of the male connectors and the female connectors. And hence it becomes to be required strongly a decrease of such the force for inserting therein and for extracting therefrom in a smaller space of such as the inside of the engine room of the motor vehicle or the like in particular, due to a difficulty of a working for inserting and for extracting therein.

35 **[0005]** Here as a method in order to reduce such the above mentioned force for inserting therein and for extracting therefrom, there is provided a method to weaken a pressure of a contact to between each of the terminals. However, there may be occurred a failure in electrical conduction of between each of the terminals due to an occurrence of a fretting phenomenon on between the contact faces of the individual terminals in a case where such the method is adopted therefor.

40 **[0006]** Moreover, such the above mentioned fretting phenomenon is the phenomenon that a plating layer of Sn as a soft layer on a surface of a terminal becomes to be worn away and to be oxidized and then to be a abrasion powder that has a specific resistance as larger, due to a slight sliding that is generated on between the contact faces of the individual terminals because of such as a vibration thereon or variation of a temperature thereof or the like. And then thereby there becomes to be occurred the failure in connection of therebetween in the case where there is occurred such the phenomenon at between each of the terminals. Further, the lower the pressure of the contact to between each of the terminals the easier there becomes to be occurred such the phenomenon. Still further, there may become to be difficult for such the phenomenon to occur by designing a thickness of the plating layer of Sn as thinner on each of the surfaces of the individual terminals in the connector, however, it is difficult to prevent completely from occurring such the phenomenon.

50 **[0007]** Still further, there is proposed the method in order to preventing from such the above mentioned fretting phenomenon that is for forming an intermetallic compound layer of Cu-Sn as a harder layer on a base material, such as a Cu_6Sn_5 or the like, and then that it is further difficult for such the fretting phenomenon to be occurred thereby (refer to the following Patent Document 5 and 6 for example). However, there is a problem in accordance with such the method that there is a case where such the intermetallic compound layer of Cu-Sn becomes to be embrittled due to a diffusion of any elements of the base material as a large amount thereof, such as the Cu therein or the like, into such the intermetallic compound layer of Cu-Sn.

55 **[0008]** Still further, there is disclosed the metallic material in which there is designed to be provided a layer of Ni in

between the above mentioned substrate and the intermetallic compound layer of Cu-Sn in order to prevent from the diffusion of any elements from the substrate (refer to the following Patent Document 7 for example). However, there is not designed to be existed any layer of Sn or any layer of Cu in between the layer of Ni and the intermetallic compound layer of Cu-Sn. And then thereby there becomes to be required a lot of extra works on a production of such the metallic material in a case where such the production thereof is performed by processing the plating of Ni and of Cu and then of Sn in order as a layered structure onto a substrate and then by processing a heat treatment therefor, because it is necessary to design exactly each of the thicknesses of the plating regarding such the layered body by plating with being based on the stoichiometric proportion of between the Cu therein and the Sn therein, and also because it is necessary to perform such the process of the heat treatment therefor under a thorough control as well.

[0009] Furthermore, there is proposed the structure of which there is formed an intermetallic compound layer of Cu-Sn as a harder layer on a base material, such as a Cu_6Sn_5 or the like, and then there is designed to be attached such as a bulk of Sn onto a part of a surface thereof (refer to the following Patent Document 8 for example). However, it is not different as substantially from the technologies in accordance with the above mentioned Patent Document 1 to 4 from a point of view of the occurrence of the fretting phenomenon at between each of the contact faces of the individual terminals due to such the bulk of Sn as a softer body.

[Patent Document 1] Japanese Patent Application Publication No. 2004-179055

[Patent Document 2] Japanese Patent Application Publication No. 2000-021545

[Patent Document 3] Japanese Patent Application Publication No. 2003-082499

[Patent Document 4] Japanese Patent Application Publication No. 2004-339555

[Patent Document 5] Japanese Patent Application Publication No. 2000-212720

[Patent Document 6] Japanese Patent Application Publication No. 2000-226.645

[Patent Document 7] Japanese Patent Application Publication No. 2004-068026

[Patent Document 8] Japanese Patent Application Publication No. 2003-213486

[0010] US 2003 091855 discloses a metallic material for a connector according to the preamble of claim 1.

Disclosure of the invention

[0011] Different aspects of the invention are disclosed in the claims.

[0012] The above and other aspects and advantages in accordance with the present invention will be further clarified by the following description, in reference to the drawings that are attached as properly therefor.

Brief description of the drawings

[0013]

FIG. 1 is a diagrammatic perspective view showing a male terminal in a connector regarding one embodiment in accordance with the present invention.

FIG. 2 is a diagrammatic perspective view showing an internal structure of a female terminal in the connector regarding one embodiment in accordance with the present invention.

FIG. 3 is a schematic drawing of cross section showing a state of connection of a connector in accordance with the present invention.

FIG. 4 is an explanatory drawing from a diagrammatic perspective view showing one embodiment regarding a metallic material in accordance with the present invention.

FIG. 5 is an explanatory drawing from a diagrammatic perspective view showing a layered body by plating to be made use for a production of a metallic material in accordance with the present invention.

FIG. 6 is an SEM photograph by making use of an AES instrument showing one example regarding a measuring region.

FIG. 7 is a picture showing an image by mapping (Sn-Cu-Ni map) obtained by making use of the AES instrument regarding the measuring region as shown in FIG. 6.

FIG. 8 is a picture showing an image by mapping (Sn map) obtained by making use of the AES instrument regarding the measuring region as shown in FIG. 6.

FIG. 9 is a picture showing an image by mapping (Cu map) obtained by making use of the AES instrument regarding the measuring region as shown in FIG. 6.

FIG. 10 is a picture showing an image by mapping (Ni map) obtained by making use of the AES instrument regarding the measuring region as shown in FIG. 6.

FIG. 11 is another SEM photograph by making use of the AES instrument showing one example regarding another measuring region.

FIG. 12 is a picture showing an image by mapping (Sn-Cu-Ni map) obtained by making use of the AES instrument regarding the measuring region as shown in FIG. 11.

FIG. 13 is a picture showing an image by mapping (Sn map) obtained by making use of the AES instrument regarding the measuring region as shown in FIG. 11.

FIG. 14 is a picture showing an image by mapping (Cu map) obtained by making use of the AES instrument regarding the measuring region as shown in FIG. 11.

FIG. 15 is a picture showing an image by mapping (Ni map) obtained by making use of the AES instrument regarding the measuring region as shown in FIG. 11.

FIG. 16 is a schematic plan view showing one example regarding a distribution of an alloy of Cu-Sn on a surface of an alloy layer of Cu-Sn and a distribution of Sn thereon, that corresponds to one part of the measuring region as shown in FIG. 11.

FIG. 17 is a schematic plan view showing another example regarding another distribution of the alloy of Cu-Sn on the surface of the alloy layer of Cu-Sn and another distribution of Sn thereon, that corresponds to another part of the measuring region as shown in FIG. 11.

FIG. 18 is an explanatory drawing from a diagrammatic perspective view showing a method for testing a slight sliding.

FIG. 19 is an explanatory drawing showing a test of a force for inserting thereinto in accordance with Example 2.

FIG. 20 is a circuit diagram showing a test for measuring a value of resistance in accordance with Example 2.

Best mode for carrying out the invention

[0014] Here a connector in accordance with the present invention is the connector in which there are designed to be arranged a male connector that comprises a male terminal and to be arranged a female connector that comprises a female terminal as connectable with each other, and that there is designed to be formed a most surface layer on at least one of such the male terminal and the female terminal with making use of a metallic material as an alloy layer of Cu-Sn. Moreover, there are designed to be arranged such the male terminals as not less than one in general by being housed individually in a housing (not shown in any of the figures) regarding the male connector that comprises such the male terminal. Further, there are designed to be arranged such the female terminals as not less than one in general by being housed individually in a housing (not shown in any of the figures either) regarding the female connector that comprises such the female terminal as similar thereto. Still further, the matter regarding the connector is the general matters in accordance with the present invention, and then any showing in the figures and further detailed description are omitted thereby.

[0015] Still further, there is designed to be produced the above mentioned metallic material as preferably by performing

a plating of an element, such as Ni or Cu or Sn or the like as principally, onto such as an electrically conductive base material or the like. Furthermore, regarding a nature of such the plating thereon, a configuration of the individual thicknesses of the plating thereon, whether or not performing a process of a heat treatment therefor, an amount of time at a temperature of the process of the heat treatment therefor in a case of performing such the process of the heat treatment therefor, whether or not performing a process of cooling therefor, an amount of time for performing the process of cooling therefor in a case of performing such the process of cooling therefor, or the like, it is designed therefor individually to be set as properly with corresponding to a manufacturing cost in total and with corresponding to quality of a part as required that is to be made use therefor.

[0016] Here FIG. 1 is a diagrammatic perspective view for showing a male terminal 10 in a connector regarding one embodiment in accordance with the present invention. Moreover, such the male terminal 10 comprises a tab 11 as a part for connecting with a female terminal 20 and a wire barrel 12 as a part for jointing by pressing in order to perform a jointing by pressing with an electric wire. Further, there is designed to be formed such the tab 11 as a flat plate shape, and then there is designed to be finished the same with an upper surface thereof and a lower surface thereof to be the individual surfaces as smooth respectively.

[0017] Still further, FIG. 2 is a diagrammatic perspective view for showing an internal structure of a female terminal 20 in the connector regarding one embodiment in accordance with the present invention. And then such the male terminal 10 as shown in FIG. 1 and the female terminal 20 as shown in FIG. 2 are designed to be as connectable with reach other and designed to comprise the connector therein. Still further, a contact member part in the female terminal 20 for the male terminal 10 in accordance with FIG. 2 is designed to be as a hollow box type, and then there is provided a ligulate piece 21 and a dimple 22 and a bead 23 at an inner side thereof.

[0018] Still further, such the dimple 22 is the member of convex shape that is designed to be arranged on an upper part of the ligulate piece 21, and then that is designed to be point contacted with a lower surface of the tab 11 at a period of the connection to the male terminal 10. Still further, such the ligulate piece 21 is designed to have a function as a spring to function a contact pressure, that is to say, a pressure to push the dimple 22 toward the tab 11. Furthermore, the bead 23 is the member of convex shape as well, and then that is designed to be contacted to the upper surface of the tab 11 and then to be received the contact pressure of which such the dimple 22 forces toward the tab 11.

[0019] Here regarding at least a part of at least one of the male terminal 10 and the female terminal 20, a most surface thereof is designed to be formed with making use of a metallic material as an alloy layer of Cu-Sn. Moreover, there may be designed to be formed only a part of the male terminal 10 and/or of the female terminal 20 with making use of the above mentioned metallic material. And then it is desirable to be formed at least the contact member part with making use of the above mentioned metallic material in such the case thereof. Further, it is desirable only for the male terminal 10 to be as the alloy of Cu-Sn rather than only for the female terminal 20 to comprise the alloy layer of Cu-Sn in a case where there is designed to be formed the most surface layer on either one of the male terminal 10 or the female terminal 20 with making use of the metallic material as the alloy layer of Cu-Sn. And then it is further preferable for both of the male terminal 10 and the female terminal 20 to be as the alloy of Cu-Sn.

[0020] Furthermore, a state of the most surface layer of the metallic material is defined here to be as an initial state for a connector in a case where such the metallic material is designed to be made use for the connector in accordance with the present invention.

[0021] Next, in a case of connecting the male terminal 10 to the female terminal 20 there is designed to insert the tab 11 into a space between the ligulate piece 21 and the bead 23 as shown in the schematic drawing of cross section of FIG. 3. Moreover, there is designed to be contacted as slidable the bead 23 onto the upper surface of the tab 11 and there is designed to be contacted as slidable the dimple 22 onto the lower surface of the tab 11 as well in the case thereof. And then at a period of inserting the tab 11 thereinto completely there is designed to be contacted and held the tab 11 with being pressed against and at between the bead 23 and the dimple 22 under a state where each of such the members is contacted with the tab 11 respectively. And hence there is designed to be performed a connection as electrically between the male terminal 10 and the female terminal 20 thereby.

[0022] Further, there is designed for the upper surface of such the tab 11 and the lower surface thereof to be individual contact member parts regarding a side on the male terminal 10 in the case where there is performed the connection of therebetween in such the manner. Still further, there is designed for the dimple 22 and the bead 23 to be individual contact member parts regarding a side on the female terminal 20 on the contrary thereto.

[0023] Furthermore, in a case where there is a difference on a hardness of the individual surfaces of between the male terminal 10 and the female terminal 20, the softer surface thereof becomes to be rubbed worn away easier, and then the smaller an amount of such the part to be worn away the smaller the force for inserting thereinto. And hence with taking into consideration of such the matter, it is desirable to harden a material at a side of which a contact area thereof as larger with corresponding to a locus of the individual contact member parts for each of the male terminal and the female terminal at the period of the connection to therebetween. And then thereby it becomes possible to reduce a resistance for inserting the connector thereinto and extracting therefrom, and it becomes possible to reduce the force for inserting thereinto as well that is required at a time of assembling the connector. And it becomes possible to improve

labor effectiveness on working for assembling thereof as well, and hence it becomes possible to reduce a tiredness of such a worker therefor.

[0024] Next, regarding a connector in accordance with another embodiment as preferred to the present invention, there is designed to be provided a male terminal and a female terminal that are connectable to each other, and there is designed to be formed all over a surface of the terminal regarding either one of the above mentioned male terminal or the above mentioned female terminal or to be formed at least a contact member part of the same with making use of a metallic material on which a most surface thereof is designed to be comprised of an alloy layer of Cu-Sn, and also there is designed to be formed at least a contact member part of the other one of the above mentioned male terminal or the above mentioned female terminal with making use of a metallic material on which a most surface thereof is designed to be comprised of a layer of Sn or an alloy layer of Sn. Here in accordance with such the male terminal there may be a probability to occur with an area as larger regarding the fretting phenomenon or a forming of a pure layer of Sn which is a cause of the force for inserting therein as higher, due to the contact member part thereof as a flat plate shape. Moreover, in the case of the female terminal on the contrary thereto, such the area thereof becomes to be smaller due to the contact member part thereof as a hemispherical shape. Therefore, it is desirable for the above mentioned most surface of the male terminal to be comprised of the alloy layer of Cu-Sn, and for the above mentioned most surface of the female terminal to be comprised of the layer of Sn or of the alloy layer of Sn.

[0025] Further, regarding the connector in accordance with the present embodiment, there is designed for the male terminal to be as the terminal that has the surface to be harder as the side for the above mentioned contact member part thereof to have the contact area as larger, and there is designed for the female terminal to be as the terminal that has the surface to be softer as the side for the above mentioned contact member part thereof to have the contact area as smaller, with taking into consideration of the locus of such the individual contact member parts for each of the male terminal and the female terminal at the period of the connection to therebetween. And then thereby it becomes able to reduce the amount of the part to be worn away (per a unit area) from the surface for such the contact member part thereof to have the contact area as larger, and hence it becomes able to enhance the effect of reducing the force for inserting therein.

[0026] Still further, there is designed to be formed the male terminal in general with having the flat shape in order to insert with ease therein. Still further, there is designed to be formed the female terminal on the contrary thereto with having a shape by which the same become to have a function as a spring by being performed a process of bending work onto either one of an upper side of an inner surface thereof or a lower side thereof or both of such the sides thereof. Still further, there is designed to be formed the contact member part at the side on the female terminal as being protruded toward the side on the male terminal in general. And then thereby there may be a case where such the male terminal is produced by punching out a flat plate directly, meanwhile, there are a large number of cases where such the female terminal is produced by performing a process of bending therefor. And hence it is desirable for such the female terminal to comprise the metallic material with having the hardness as softer than that of the male terminal from a point of view of the easiness on processing therefor. Thus, in a case of further performing a process of bending thereof in accordance with a further strict specification in particular in order to correspond to a demand as smaller in size thereof in the recent years, it is further preferable to apply the present invention thereto that comprises such the female terminal with which it becomes able to perform such the process as easier.

[0027] Still further, there becomes another reason in addition thereto that it is effective to select the male terminal as an object to be performed a process of hardening in accordance with the present embodiment, because the contact area of the male terminal with corresponding to the locus of the contact member part thereof becomes to be larger than the contact area of the female terminal with corresponding to the locus of the contact member part thereof regarding the insertion of such the terminal therein with taking into consideration of the configuration thereof.

[0028] Furthermore, there is designed for such the connector to be mounted onto a motor vehicle as a connector for being mounted on a motor vehicle for instance. However, the usage of such the connector in accordance with the present invention is not limited to the connector for being mounted on a motor vehicle, and then it is possible to apply the same to any connector for any other usage of such as an electrical device or an electronic device or the like.

[0029] Next, a metallic material for a connector that comprises the connector in accordance with the present invention will be described in detail below.

[0030] Here the metallic material for the connector in accordance with the present invention is the metallic material to form at least a part of a male terminal or a part of a female terminal in an electrical device or in an electronic device, in which there is provided an alloy layer of Cu-Sn on a most surface thereof. Moreover, there is designed therefor as preferred to be made use of such as a material in which a concentration of Cu is designed to be decreased gradually toward the surface thereof, a material in which Sn or an alloy of Sn is designed to be diffused into an alloy layer of Cu-Sn, or the like. Further, it may be available to design for such the Sn therein or the alloy of Sn therein as a part thereof to be exposed from the surface of the alloy layer of Cu-Sn.

[0031] Still further, there is no limitation in particular regarding a layer that is directly under a region where there is designed to be provided such the above mentioned alloy layer of Cu-Sn. And then there may be available therefor to

be provided such the alloy layer of Cu-Sn onto an electrically conductive substrate for instance, or there may be available therefor to be provided a metal layer or an alloy layer, that is comprised of any one type or any two types selected from Cu, an alloy of Cu, Ni, an alloy of Ni, Fe, an alloy of Fe, Co and an alloy of Co, onto an electrically conductive substrate and then to be provided such the alloy layer of Cu-Sn thereto as the above mentioned most surface thereof.

[0032] Here FIG. 4 is a drawing from a diagrammatic perspective view for showing a metallic material for a connector regarding one embodiment as preferably in accordance with the present invention, wherein such the metallic material for the connector 5 comprises an electrically conductive substrate 1, an underlayer 2 which is comprised of Ni and is provided thereto, an intermediate layer 3 which is comprised of Cu and is provided thereto, and an alloy layer of Cu-Sn 4 which is provided thereto.

[0033] Moreover, such the metallic material for the connector 5 is designed to be produced by such as the following processes of: performing a process of plating for forming a layer of Ni (an N-layer) 2a, a layer of Cu (a C-layer) 3a and a layer of Sn (an S-layer) 4a in order onto an electrically conductive substrate 1 as shown in a drawing from a diagrammatic perspective view of FIG. 5 in order to form a layered body by plating 6; performing each of the diffusions of the Cu in the above mentioned C-layer 3a and the Sn in the above mentioned S-layer 4a by performing a process of treating with heat therefor; and then forming an alloy layer of Cu-Sn on a most surface thereof by performing a reaction therebetween. Further, there is designed to be prevented a thermal diffusion of any of the elements from the base substrate by making use of the N-layer 2a on the contrary thereto at the period of performing such the process of treating with heat therefor. Still further, there is designed to be determined a volume ratio as an S/C of between a volume of the S-layer 4a and that of the C-layer 3a, with taking into consideration of a thickness of the alloy layer of Cu-Sn 4 that is required therefor, in order to design the S-layer 4a therein to be disappeared after performing the process of treating with heat therefor, and in order to design the C-layer 3a therein to be remained thereafter as an intermediate layer therein on the contrary thereto. Still further, it is not necessary for a thickness of the above mentioned C-layer 3a (the thickness of the intermediate layer 3) in particular therein after performing the process of treating with heat therefor to be specified as strictly on the contrary thereto. And hence it becomes able to perform as easily the designing of the layered body by plating 6 and to perform the process of treating with heat therefor. And therefore it becomes able to obtain the metallic material for the connector 5 in accordance with the present invention with an ease of the production therefor and with being superior in productivity thereof.

[0034] Still further, it is desirable to perform a process of cooling therefor after performing the above mentioned process of treating with heat therefor in the case of forming the alloy layer of Cu-Sn as the most surface thereof by performing the diffusion of between the Cu in the above mentioned C-layer 3a and the Sn in the S-layer 4a. And then by performing such the process of cooling therefor under a condition as properly therefor, it becomes possible to form the alloy layer of Cu-Sn as a gradation like structure therein in place of a layered structure therefor regarding such the diffusion of between the Cu therein and the Sn therein. Still further, it becomes able to form such the alloy layer of Cu-Sn with remaining a pure Sn on the most surface thereof and with remaining the same as partially thereon as well.

[0035] Still further, it may be able to perform the above mentioned process of treating with heat therefor by making use of any of the methods therefor, however, it is desirable for such the process to be designed by which there becomes to be passed the layered body by plating 6 through an inside of a reflow furnace with a temperature at the inside of the furnace of between 300 °C and 800 °C and with an amount of time for three seconds and twenty seconds.

[0036] Still further, it may be able to perform the above mentioned process of cooling therefor by making use of any of the methods therefor, however, it is desirable for such the process to be designed by which there becomes to be performed by being passed such the layered body through an inside of a liquid mass with a temperature of between twenty °C and eighty °C and with an amount of time for between one second and 100 seconds thereafter, or it is more desirable therefor to be performed by being passed through an inside of a gaseous body with a temperature of between twenty °C and sixty °C and with an amount of time for between one second and 300 seconds thereafter and then therefor to be performed by being passed through an inside of a liquid mass with a temperature of between twenty °C and eighty °C and with an amount of time for between one second and 100 seconds thereafter. Furthermore, it is further preferable therefor to be performed by being passed through an inside of a liquid mass with a temperature of between thirty °C and fifty °C and with an amount of time for between five seconds and fifteen seconds thereafter.

[0037] Next, there is designed for a thickness of the C-layer 3a in the layered body by plating 6 to be as not less than 0.01 μm in general. Moreover, it is desirable for an upper limit therefor to be as approximately 5.0 μm , with taking into consideration of such as a point of view of a practical aspect thereof, a cost of the materials therefor, a cost of the production therefor, or the like. Further, it is further preferable for such the thickness of the C-layer 3a therein to be as not thinner than 0.05 μm but not thicker than 0.5 μm . Furthermore, there may be occurred micro-pores as a large number thereof in the C-layer (intermediate layer 3) after performing the process of treating with heat therefor in a case where there is designed to be made use of Cu for such the C-layer 3a and then where such the Cu layer 3a is thinner therein. And then thereby there may be a case to be happened that the barrier function as the intermediate layer is lost therefrom. And hence it is further preferable for such the thickness of the C-layer 3a to be as slightly thicker in the case where there is designed to be made use of Cu, which is compared to that in a case where there is designed to be made use of an

alloy of Cu therefor.

[0038] Next, regarding the S-layer 4a in accordance with the present invention, it is required an amount of time as longer with depending on a thickness thereof for such the S-layer 4a to be reacted completely therein. And then after a process of treating with heat therefor there may be a case where the Sn therein is diffused into the alloy of Cu-Sn 4 and then is remained therein with having a punctuate shape or an island shape. However, there is seldom happened for the function of the metallic material for the connector 5 to be worsened due to such the case thereof. Moreover, there may be a case where a part of the Sn or the alloy of Sn that is diffused thereinto becomes to be exposed onto the surface of the alloy layer of Cu-Sn 4 in such the above mentioned case thereof. And then in such the case thereof it is desirable for an exposed area of the Sn or of the alloy of Sn that is exposed thereto to be as sufficiently smaller comparing to an area of the faces in total of the Sn or the alloy of Sn that is diffused thereinto.

[0039] Further, it is not desirable for a product which is finished the process of the treatment of reflow therefor in a case where there is remained the C-layer 3a as excessively thicker on the underlayer, due to a case in general where there may be diffused such the excessive element from the layer to the surface at a time when the same receives a thermal load, and then due to a case where there may become a cause, to happen an oxidation thereof and an increase of the resistance thereof. However, in a case on the contrary thereto where there is existed the Cu-Sn on the most surface layer thereof and also the pure Sn is diffused or remained therein, there becomes to be received the diffusion of such the Cu that is remained as excessively in the underlayer by such the pure Sn therein, and then thereby it becomes possible to suppress the diffusion of the copper therefrom to the most surface thereof, to suppress the oxidation thereof and then to suppress the increase of the resistance thereof.

[0040] Still further, it becomes possible for the diffused Sn thereinto to react with such the excessive amount thereof and then to further diffuse such the Sn thereinto in such the case where there is designed to be diffused such the Sn into the alloy layer of Cu-Sn 4 as the most surface layer even if there is designed to be remained the Cu layer (intermediate layer) 3 as thicker. Furthermore, an effect of such the diffusion thereinto is remarkable under an environment with a temperature as higher. And hence it becomes possible to obtain a domain for a designing of condition as wider regarding the plating thereon and the production thereof, and then thereby it becomes possible to maintain the individual properties thereof with an amount of time for longer even under such the environment with the temperature as higher.

[0041] Thus, such the above mentioned material in which the Sn or the alloy of Sn is designed to be diffused into the alloy layer of Cu-Sn 4 is one embodiment regarding the metallic material in accordance with the present invention as well. Here the Sn or the alloy of Sn that is diffused as the punctuate shape or as the island shape from the point of view of cross section is defined that a rate of occupation regarding an area of the Sn or of the alloy of Sn in the alloy layer of Cu-Sn, which is approximately equivalent to a rate of occupation regarding a volume thereof, to be as between zero percent and sixty percent in accordance with an image by mapping that is obtained by making use of such as an instrument of an Auger electron spectroscopy (AES) or the like. Moreover, regarding such the Sn or the alloy of Sn that is diffused as the island shape from the point of view of cross section, there is existing a case where a part thereof to be exposed onto the most surface thereof, meanwhile, there is existing another case, as well where there is none of the part thereof to be exposed onto the most surface thereof. As a typical example, regarding such the case where the part thereof to be exposed onto the most surface thereof, there is existing a part of the alloy of Cu-Sn at the inside of the Sn or the alloy of Sn that is exposed onto the most surface thereof from the point of view of cross section, meanwhile, there is existing the Sn or the alloy of Sn with having a doughnut shape from a point of view of plane for the most surface thereof on the contrary thereto. And then there is no problem at all for the Sn or the alloy of Sn to be dissolved and then removed therefrom by making use of an agent, that is remained only in the vicinity of the surface thereof among the Sn or the alloy of Sn that is diffused and then remained in the above mentioned alloy layer of Cu-Sn 4. Furthermore, there may be a case as preferred to remove such the Sn or the alloy of Sn that is remained only in the vicinity of the surface of the above mentioned alloy layer of Cu-Sn 4, because such the case becomes to be a cause for the fretting phenomenon which is described above in a case where there is existing such the Sn or the alloy of Sn at a state as sticking out from the surface of the alloy layer of Cu-Sn 4 with a larger amount thereof.

[0042] Here each of FIG. 6 through FIG. 10 is a picture for showing an image by mapping that is obtained by making use of the instrument of the AES for one sample regarding the metallic material in accordance with the present invention. And first of all there is obtained the sample with an oblique section of thirty degrees by making use of a focused ion beam (FIB) with setting such the sample to be inclined as sixty degrees, and such the sample is assumed to be as a sample for an Auger analysis and measurement (AES). Moreover, there is performed such the AES with such the sample to be inclined for having the oblique section of thirty degrees to become horizontal. And hence there becomes to be obtained each of such the electron images of the AES therein. Further, it is found out in the alloy layer of Cu-Sn as the most surface layer thereon that there is existed an intermetallic compound of Cu-Sn together therewith, such as Cu₃Sn or Cu₄Sn or the like.

[0043] Still further, FIG. 6 is an SEM photograph (having a width of 11.7 μm) for showing a measuring region of the AES measurement therefor on a cross section of the sample. Still further, each of FIG. 7 through FIG. 10 is a picture for showing an image by mapping regarding a metallographic structure of the measuring region thereof as shown in

FIG. 6. And then FIG. 7 is an Sn-Cu-Ni map for showing the Sn therein, the Cu therein and the Ni therein with making use of lightness and darkness of color as different from each other, meanwhile, FIG. 8 is an Sn map for showing the Sn therein with making use of white color, meanwhile, FIG. 9 is a Cu map for showing the Cu therein with making use of white color, meanwhile, FIG. 10 is an Ni map for showing the Ni therein with making use of white color.

[0044] Still further, the symbol of 31 designates a surface of the alloy layer of Cu-Sn (outermost layer) in accordance with each of FIG. 7 through FIG. 10, the symbol of 32 designates a substrate therein, the symbol of 33 designates an underlayer therein, the symbol of 34 designates an intermediate layer therein, and the symbol of 35 designates the alloy layer of Cu-Sn (outermost layer) therein. Still further, there is shown the alloy layer of Cu-Sn 35 with making use of white color in accordance with FIG. 8, and then a part at a side for the surface 31 as further brighter indicates that there is contained Sn therein as a larger number thereof. Still further, there is shown the underlayer 33 with making use of black color in accordance with FIG. 9, and then which indicates that there is not contained substantially any Cu in such the underlayer 33. Still further, there is shown only the underlayer 33 with making use of white color in accordance with FIG. 10, and then which indicates that there is not diffused the Ni into any other region except such the underlayer 33. Still further, it is found out as shown in each of FIG. 7 through FIG. 10 that there is seldom remained the Sn or the alloy of Sn at the inside of the alloy layer of Cu-Sn 35 (an area that the Sn therein or the alloy of Sn therein occupies is determined to be as between zero percent and ten percent). Still further, it is found out as shown in FIG. 9 that there is decreased gradually the Cu therein toward the surface thereof.

[0045] Next, each of FIG. 11 through FIG. 15 is a picture for showing an image by mapping for another sample regarding the other metallic material in accordance with the present invention, which is obtained by making use of the instrument of the AES as similar to that in accordance with each of FIG. 7 through FIG. 10. Still further, FIG. 11 is an SEM photograph (having a width of 11.7 μm) for showing a measuring region of the AES measurement therefor on a cross section of the sample. Still further, each of FIG. 12 through FIG. 15 is a picture for showing an image by mapping regarding a metallographic structure of the measuring region thereof as shown in FIG. 11. And then FIG. 12 is an Sn-Cu-Ni map for showing the Sn therein, the Cu therein and the Ni therein with making use of lightness and darkness of color as different from each other, meanwhile, FIG. 13 is an Sn map for showing the Sn therein with making use of white color, meanwhile, FIG. 14 is a Cu map for showing the Cu therein with making use of white color, meanwhile, FIG. 15 is an Ni map for showing the Ni therein with making use of white color. Still further, the symbol of 31 designates a surface of the alloy layer of Cu-Sn in accordance with each of FIG. 11 through FIG. 15, the symbol of 32 designates a substrate therein, the symbol of 33 designates an underlayer therein, the symbol of 34 designates an intermediate layer therein, and the symbol of 35 designates the alloy layer of Cu-Sn therein. Still further, there is shown Sn or an alloy of Sn 36 to be diffused as an island shape into the alloy layer of Cu-Sn 35 in accordance with FIG. 12 as shown with making use of a further darker color therein. Still further, there is shown the alloy layer of Cu-Sn 35 as further brighter in accordance with FIG. 13, and then which indicates that there is contained the Sn or the alloy of Sn 36 in a part as an island shape with making use of a further white color at a side for the surface 31 thereof. Still further, there is shown the underlayer 33 and the Sn or the alloy of Sn 36 as an island shape in accordance with FIG. 14, and then which indicates that there is not contained substantially any Cu in each of such the regions thereof respectively. Still further, there is shown only the underlayer 33 with making use of white color in accordance with FIG. 15, and then which indicates that there is not diffused the Ni into any other region except such the underlayer 33.

[0046] Still further, it is found out as shown in FIG. 12 through FIG. 15 that an area of the region where there is occupied by the Sn or the alloy of Sn in the alloy layer of Cu-Sn on the layer of Ni is between thirty percent and sixty percent therein in total. Still further, it is found out that there is decreased gradually the Cu therein toward the surface thereof.

[0047] Still further, in accordance with the metallic material as the present sample therefor, there is diffused the Sn or the alloy of Sn 36 as the island shape into the alloy layer of Cu-Sn 35 from the view of cross section as shown in FIG. 12, and then there becomes to be exposed the part of the Sn or the alloy of Sn 36 as the island shape onto the surface 31 of the alloy layer of Cu-Sn 35. Still further, there is existed the part of the alloy of Cu-Sn at the inside of the Sn or of the alloy of Sn that is exposed on the alloy layer of Cu-Sn as schematically shown in FIG. 16 and in FIG. 17, that there is exposed such the Sn or the alloy of Sn as approximately looked like a doughnut shape from a point of view of the surface thereof. Still further, the number 4 in accordance with FIG. 16 and with FIG. 17 designates a metal layer of Cu-Sn by plating on the most surface thereof, the number 4b therein designates an intermetallic compound of Cu-Sn, and the number 4c therein designates a part of the Sn or the alloy of Sn by which there is formed the layer of Sn (the S-layer) in accordance with FIG. 2. Still further, such the intermetallic compound of Cu-Sn 4b therein becomes to form a part of the layer of the most surface thereof by being combined with the alloy layer of Cu-Sn 4.

[0048] Still further, there becomes to be generated such a state thereof in a case where the volume ratio of between the volume of the S-layer in the layered body by plating and that of the C-layer therein to be as smaller than 1.90, which is the condition that there is not remained any of the layer of Sn on the surface of the metallic material in the case where whole of the Sn therein become to be alloyed as Cu-Sn, and in a case where there is designed to be finished the process of treating with heat therefor by performing such as a process of quenching rapidly therefor under a state that there is not completely alloyed the Sn therein to become Cu-Sn as well. And then in accordance with such the state thereof,

there becomes to be contacted the alloy of Cu-Sn to such as the contact member part thereof or the like, that is existing around the Sn or the alloy of Sn which is exposed onto the surface of the alloy layer of Cu-Sn, and that is further harder than such the Sn thereon or the alloy of Sn thereon. And hence it becomes able to prevent such the Sn thereon or the alloy of Sn thereon that becomes to be exposed onto the surface of the alloy layer of Cu-Sn from being worn away as less as possible. And then thereby there becomes to be less affected by the fretting phenomenon. Furthermore, it becomes able to obtain a further advantage that there becomes to be stabilized the contact resistance of therebetween, because there is remained a margin that there becomes to be reacted to between the Cu which is existing at a side for a lower layer of the alloy layer of Cu-Sn and the Sn or the alloy of Sn which is diffused into the inside of such the alloy layer of Cu-Sn at a period of maintaining such the material at a temperature therefor as higher and then that there becomes to be further formed an alloy of Cu-Sn therein, and then because there becomes not to be formed any of such as CuO or the like on the surface thereof.

[0049] Here in accordance with the present invention, there is no limitation in particular regarding a thickness of the intermediate layer 3 in the metallic material for the connector 5. However, it is desirable therefor to be as between 0.01 μm and 1.0 μm , or it is further preferable therefor to be as between 0.05 μm and 0.5 μm . Moreover, there is no limitation in particular regarding a thickness of the alloy layer of Cu-Sn 4 in the metallic material for the connector 5 in accordance with the present invention. However, it is desirable therefor to be as between 0.05 μm and 2.0 μm , or it is further preferable therefor to be as between 0.1 μm and 1.0 μm .

[0050] Further, there is designed to be provided such the intermediate layer 3 which is comprised of copper or the alloy of copper in such the metallic material for the connector 5 in accordance with the present invention. And then there is seldom worsened such as the properties of inserting thereinto and extracting the terminal thereinto or the like, regarding such the metallic material therein even in a case where there may be assumed for the C-layer 3a to be disappeared therefrom together with the S-layer 4a after performing the process of treating with heat for the above mentioned layered body by plating 6.

[0051] Still further, it is desirable for the alloy layer of Cu-Sn by plating as the most surface thereof in accordance with the present invention to be designed as decreasing the concentration of Cu therein as gradually from a side for the substrate toward the surface thereof. And then in such the case thereof there becomes not to be formed clearly a boundary of between such the alloy layer of Cu-Sn and the layer of Cu which is existing under such the alloy layer or a boundary of between such the alloy layer and the substrate.

[0052] Still further, it is able to design to obtain a distribution of the above mentioned concentration of the Cu therein as both of a distribution of the concentration thereof in a layered formation and a distribution of the concentration thereof in a gradation like formation by controlling a condition of the production therefor. And then it is further preferable therefor to be designed as the gradation like formation from a point of view of the easiness regarding the production therefor.

[0053] Still further, it becomes able to design to obtain the metallic material in accordance with the present invention that comprises the contact member part in the terminal on which there is designed for the most surface thereof to be as the alloy layer of Cu-Sn with decreasing gradually the concentration of the Cu therein toward the surface thereof and that comprises a joint part for electric wire by pressing to be as the layer of Sn. And then it becomes able to produce such the metallic material in accordance with such the aspect thereof by performing a process of plating the S-layer as thinly at which there is designed for a part thereof to be as the above mentioned contact member part in the terminal thereon with making use of such as a masking therefor or the like, and then by performing a process of plating the S-layer as thickly at which there is designed for a part thereof to be as the above mentioned joint part for electric wire by pressing and then thereafter by performing a process of treating with heat therefor. And therefore it becomes able to produce such the metallic material as easier in accordance with such the method therefor, on which the material on the most surface thereof is different thereby from region to region thereon.

[0054] Still further, in a case of performing the process of treating with heat for the above mentioned layered body by plating 6 by making use of a reflow treatment (continuous processing), it is desirable for a substantial temperature of the layered body by plating 6 to be as between 232 °C and 500 °C, with an amount of time for between 0.1 second and ten minutes, or therewith for not longer than 100 seconds as it is more desirable therefor, or therewith for not longer than ten seconds as it is further preferable therefor. Still further, there becomes to be realized such the process of the reflow treatment by performing a heating therefor with maintaining a temperature at an inside of a reflow furnace as between 500 °C and 900 °C, and with an amount of time for not longer than ten minutes for instance, or therewith for not longer than ten seconds as it is more desirable therefor. And then it is preferable to perform such the process of the reflow treatment therefor by performing a control of the temperature at the inside of the reflow furnace, because it is easier to perform a measurement of the temperature at the inside of the reflow furnace in practice rather than that of the temperature in accordance with the substantial temperature thereof. Still further, in a case of performing such the process thereof by making use of a batch processing therefor, it is desirable for the above mentioned layered body to be performed by being maintained in a furnace which has a temperature of between 50 °C and 250°C, with an amount of time for between several tens minutes and several hours. Furthermore, there are required for such as the temperature thereof or the amount of time for heating thereof or the like in the case of performing the process of treating with heat

therefor by making use of the reflow treatment therefor to be set as a condition that, is pursuant to such as each of the thicknesses of the N-layer 2a and the C-layer 3a and the S-layer 4a in the layered body by plating 6 or the like. And then it is able to set each of the specific conditions thereof as properly, that will be described in detail later in accordance with the following Examples.

[0055] Here in accordance with the present invention, there is designed for the electrically conductive substrate 1 to be made use as properly of such as copper, an alloy of copper, such as phosphor bronze, a brass, a white metal, a beryllium copper, a Corson alloy, or the like, iron, an alloy of iron, such as a stainless steel or the like, a composite material, such as a material of iron to be covered by copper, a material of iron to be covered by nickel, or the like, an alloy of nickel as a variety thereof, an alloy of aluminum as a variety thereof, or the like, that each of such the materials individually have the electrical conductivities and the mechanical strengths and the heat resisting properties that are required for the terminal respectively.

[0056] Moreover, it is preferable to apply the copper based material in particular of such as copper or the copper alloy or the like among the above mentioned metal and the alloys (materials), as it is superior in a balance of between the electrical conductivity thereof and the mechanical strength thereof. Further, in a case where there is designed for the above mentioned electrically conductive substrate 1 to be made use of the other material except such the copper based material, it becomes able to improve a corrosion resistance thereof and an adherence to between the underlayer 2 by being covered a surface thereof with making use of copper or an alloy of copper.

[0057] Still further, regarding the underlayer 2 to be provided onto the above mentioned electrically conductive substrate 1, there is made use as preferred thereto of such as a metal of Ni or Co or Fe, an alloy of Ni, such as a system of Ni-P, a system of Ni-Sn, a system of Co-P, a system of Ni-Co, a system of Ni-Co-P, a system of Ni-Cu, a system of Ni-Cr, a system of Ni-Zn, a system of Ni-Fe, or the like, an alloy of Fe, an alloy of Co, or the like, that individually have the barrier function to prevent any of the elements in the substrate from the occurrence of the thermal diffusion into the alloy layer of Cu-Sn 4. And then thereby it becomes able to obtain a processability of plating thereon as excellently, and there is no problem at all from a point of view of price thereof as well. Still further, it is further preferable therefor to be made use of Ni or the alloy of Ni in particular among such the elements because there is not become to be weakened the barrier function thereof even under an environment at a temperature as higher.

[0058] Still further, such the metal (alloy) of such as Ni or the like to be made use for the above mentioned underlayer 2 has a melting point as high as not lower than 1000 °C. While, a temperature of an environment for a usage of a connector to be connected is normally lower on the contrary thereto as not higher than 200 °C. And then thereby it is difficult for such the underlayer 2 to be occurred the thermal diffusion of itself. And hence it becomes able to come out the barrier function thereof as effectively. Still further, such the underlayer 2 has a further function to enhance an adherence of between the electrically conductive substrate 1 and the intermediate layer 3 with corresponding to the material to be made use for such the electrically conductive substrate 1.

[0059] Still further, regarding a thickness of such the underlayer 2, it becomes not able to function such the barrier function as sufficiently in a case where it is thinner than 0.05 μm . While, there becomes to be larger a distortion due to the plating thereon in a case where it is thicker than 3 μm on the contrary thereto. And then thereby there becomes to be peeled off as easier such the layer from the substrate. And hence it is desirable therefor to be as between 0.05 μm and 3 μm . Still further, it is more desirable for an upper limit regarding such the thickness of the underlayer 2 to be as not thicker than 1.5 μm , or it is further preferable therefor to be as not thicker than 0.5 μm , with taking into consideration of workability on the terminal.

[0060] Still further, it may be available to design such the underlayer 2 as one layer or layers as not less than two thereof. Furthermore, in a case where there is designed therefor to be the layers as not less than two thereof, it becomes able to obtain a further advantage of such as being able to set as properly such as the barrier function or the function to enhance the adherence to therebetween or the like, due to a relation to between the other layer as adjacent thereto.

[0061] Here in accordance with the present invention, it becomes able to apply an alloy of copper, such as a system of Cu-Sn or the like, in addition to copper as preferred to the intermediate layer 3 therein. And then it is desirable for a concentration of Cu in such the alloy of copper to be as not lower than fifty mass percent in such the case thereof.

[0062] Here in accordance with the layered body by plating 6 to be made use for the present invention, it is desirable for a volume ratio of between the volume of the S-layer 4a and that of the C-layer 3a that is defined as (S/C) to be as not higher than 1.85 in a case where the S-layer 4a is comprised of Sn and where the C-layer 3a is comprised of Cu. Moreover, it is desirable for a thickness of the above mentioned S-layer 4a to be as not thicker than 9.5 μm .

[0063] Further, it is able to form such as the N-layer 2a that is comprised of such as Ni or the like, the C-layer 3a that is comprised of such as Cu or the like, the S-layer 4a that is comprised of such as Sn or the like, in the above mentioned layered body by plating 6 by making use of such as a method of a physical vapor deposition (PVD) or the like. Or, it is further preferable therefor to be formed by making use of a method of wet plating thereon because it is convenient to perform and it gains a manufacturing cost as lower as well.

[0064] Here in accordance with the present invention, there is given an example for an intermetallic compound of Cu-Sn in order to form the alloy layer of Cu-Sn 4, such as a Cu_6Sn_5 , a Cu_5Sn , a Cu_4Sn , or the like. And then such the

Cu_6Sn_5 is generated by being reacted Sn as a volume of 1.90 with corresponding to a volume as one for Cu. While, such the Cu_3Sn is generated by being reacted Sn as the volume of 0.76 with corresponding to the volume as one for Cu on the contrary thereto. While, such the Cu_4Sn is generated by being reacted Sn as the volume of 0.57 with corresponding to the volume as one for Cu on the contrary thereto.

[0065] And therefore there becomes to be formed an alloy layer of Cu-Sn in which the Cu_6Sn_5 is dominant in a case of performing a process of treating with heat for a layered body by plating with an amount of time for longer, that has the volume ratio of between the volume of the S-layer 4a and that of the C-layer 3a as the (S/C) to be as between 1.90 and 1.80 for instance. While, there becomes to be formed another alloy layer of Cu-Sn in which the Cu_3Sn is dominant in a case of performing the process of treating with heat for another layered body by plating with an amount of time for longer, that has the above mentioned ratio of volumes of therebetween to be as between 0.76 and 0.70 on the contrary thereto for instance. While, there becomes to be formed another alloy layer of Cu-Sn in which the Cu_4Sn is dominant in a case of performing the process of treating with heat for another layered body by plating with an amount of time for longer, that has the above mentioned ratio of volumes of therebetween to be as between 0.57 and 0.50 on the contrary thereto for instance. Moreover, there may be a case where there becomes to be thinner a thickness of the alloy layer of Cu-Sn, or there may be a case where there becomes to be formed a layer in which there becomes to be existing together the Cu_6Sn_5 and the Cu_3Sn and the Cu_4Sn therein, due to such the reaction thereof as not to be performed completely in a case of performing the process of treating with heat therefor at a temperature as higher and of performing such the process of treating with heat therefor with an amount of time for shorter.

[0066] Further, in a case of configuring the alloy layer of Cu-Sn 4 by making use of the layers as two of the layer of Cu_6Sn_5 and the layer of Cu_3Sn in accordance with the present invention, there is no specification in particular regarding a thickness of each of such the layers therein. Or, it is further preferable for the layer of Cu_6Sn_5 therein to be as between 0.01 μm and 5.0 μm , and it is further preferable for the layer of Cu_3Sn therein to be as between 0.008 μm and 4.0 μm as well.

[0067] Still further, regarding the metallic material for the connector 5 in accordance with the present invention, there becomes not to be affected negatively onto the performance thereof even in a case where there is formed an oxide film layer which has a thickness of not thicker than 100 nm onto the surface of the alloy layer of Cu-Sn. 4. Here regarding the metallic material for the connector 5 in accordance with the present invention, there is designed for the outermost layer 4a before performing the process of treating with heat therefor to be as the Sn or the alloy of Sn, and then thereby there becomes to be formed an oxide of Sn as an oxidized substance in the case thereof. And then such the oxide of Sn has an electrical conductivity as higher comparing to that of such as an oxide of Cu or the like. And hence it may be considered that there becomes not to be affected negatively onto the electrical conductivity thereof as the metallic material. Still further, it is desirable for such the thickness of the oxide film layer thereon to be as not thicker than 30 nm.

[0068] Still further, it may be available in accordance with the present invention to design a dissimilar material as a different kind therefrom to be interjacent at between the electrically conductive substrate 1 and the underlayer 2, and/or at between the underlayer 2 and the intermediate layer 3, and/or at between the intermediate layer 3 and the alloy layer of Cu-Sn 4, that has a thickness as thinner than that of each of the layers to be adjacent thereto.

[0069] Still further, it may be available to design the alloy layer of Cu-Sn 4 to be provided onto the electrically conductive substrate 1 regarding the metallic material in accordance with the present invention, and it may be available to design such the alloy layer of Cu-Sn 4 to be provided onto the underlayer 2 which is provided on the electrically conductive substrate 1 as well.

[0070] Furthermore, it is able to adopt as arbitrarily regarding a shape of the metallic material for the connector in accordance with the present invention, such as a bar material or a plate material or the like, if such the material has a shape that forms at least a part of the male terminal in the connector and/or at least a part of the female terminal therein.

[0071] Next, there is provided a connector for another embodiment in accordance with the present invention, in which such the above mentioned metallic material for the connector configures at least a contact member part therein. And then it is desirable therefor in particular to be as a connector of a multi way type or as a contact shoe. Moreover, it becomes able to work with making use of the metallic material for the connector in accordance with the present invention into such as a connector or a contact shoe or the like for a usage of such as a motor vehicle or of an electrical device or of an electronic device or the like.

[0072] Further, it becomes able to apply such the metallic material for the connector in accordance with the present invention to either one of a side on a male terminal or a side on a female terminal or both of such the sides thereof in a case of applying such the material to the male terminal and the female terminal in an electrical component and part. Still further, there is no problem at all to apply such the material only to a part therein that is required therefor.

[0073] Still further, it becomes available in accordance with the present invention to provide the connector for an electrical device and for an electronic device, that is comprised of the male terminal and the female terminal, that becomes to be easier for the production thereof, that becomes to have the electrical connectability as further stable, and that there becomes to be improved the properties for inserting thereinto and for extracting therefrom, and it becomes available therein to provide the metallic material for a connector as well, that is made use for such the connector, and then that

becomes to be applied as preferred to such as the connect member part in the male terminal or in the female terminal or the like.

[0074] Still further, there becomes to be formed such the connector in accordance with the present invention with making use of the metallic material in which there is designed for the most surface of at least either one of the male terminal or the female terminal to be as the alloy layer of Cu-Sn. And then thereby it becomes difficult to occur the fretting phenomenon therein even in a case where there is designed for the metal layer as the most surface thereof to be as thinner and then for the contact pressure of therebetween to be as weaker. And therefore it becomes able to obtain the properties for inserting thereinto and for extracting therefrom as further excellently and the electrical connectability as further stable regarding such the connector in accordance with the present invention. Still further, it becomes able to obtain such the advantage as similar thereto in the case where there is designed for such the most surface of the contact member part of at least either one of the above mentioned male terminal therein or the above mentioned female terminal therein to be as the alloy layer of Cu-Sn in which there is designed for the concentration of Cu to be decreased as gradually. And then it is able to perform the process of treating with heat therefor with an amount of time for further shorter in a case of producing such the material as such the gradation like formation with the thickness for plating as similar to that to be produced as the layered formation and with the temperature of the heat treatment therefor as similar thereto. Or, it is able to design such the temperature of the heat treatment therefor to be as lower in a case where there is designed for an amount of time for performing such the heat treatment therefor to be as similar to therebetween as well. And hence it becomes able to obtain the further advantage that there becomes to be speeded up the production thereof or that there becomes to be reduced the cost of the heat treatment therefor.

[0075] Still further, it becomes able to enhance as locally a contact pressure against the other material as the opponent side by forming the hardness of the surface thereof to be as heterogeneous regarding the connector which is characterized in that there is designed for such the connector to comprise the male terminal and the female terminal that it is possible to connect to each other, that there is designed for all over the surface of the terminal of either one of the above mentioned male terminal or the above mentioned female terminal or at least the contact member part of either one thereof only to be formed with making use of the metallic material in which the most surface thereof is the alloy layer of Cu-Sn, and that there is designed for all over the surface of the other terminal against the either one of the above mentioned male terminal or the above mentioned female terminal or at least the contact member part of such the other terminal against the either one thereof only to be formed with making use of the metallic material in which the most surface thereof is the layer of Sn or the alloy layer of Sn. And then thereby it becomes able to ensure an electrical conduction to therebetween as certainly, and it becomes able to suppress the electrical resistance thereof as further lower as well. Still further, in the case where there is designed only for the contact member part thereof to become alloyed as Cu-Sn, it becomes able to suppress an exposure of a basic material, and it becomes able to enhance further the corrosion resistance as comparing to a case where there is designed for all of the parts therein to become alloyed as a layer of Cu-Sn as well, by designing for such as a part for bending work on such the terminal or the like to be remained pure Sn which is further softer.

[0076] Furthermore, it becomes able to form as easier the connector that has the properties as mentioned above by making use of such the metallic material for the connector in accordance with the present invention.

Examples

[0077] Next, the present invention will be described in further detail below, in reference to the following examples. However, such as each of the samples or the condition of the production therefor or the like is just a specific example therefor, and then thereby the present invention will not be limited to any one of such the examples.

(Example 1)

[0078] First of all there is performed the following process of removing a grease from a bar material of an alloy of copper (brass) which has a thickness as 0.25 mm, and then thereafter there is performed a process of acid cleaning thereof. Moreover, there is performed thereafter a production of a layered body by plating by performing a process of an electroplating of Ni and then Cu and then Sn as a layered formation in such order onto the above mentioned bar material of the alloy of copper under the following individual conditions therefor as shown in Table 1. Here such the individual conditions for plating each of the metals thereto is shown in the following Table 1.

PLATING METAL	COMPOSITION OF PLATING BATH		BATH TEMPERATURE (°C)	ELECTRIC CURRENT DENSITY (A/dm ²)
	CONSTITUENT	CONCENTRATION (g/l)		
Ni	NICKEL SULFAMATE	500	60	5
	BORIC ACID	30		
Cu	COPPER SULFATE	180	40	5
	SULFURIC ACID	80		
Sn	THE 524M SOLUTION PRODUCED BY Ishihara Chemical Co., Ltd.	-	30	5

[0079] Here there is designed for the volume ratio of between the volume of the S-layer and that of the C-layer as the (S/C) to be varied in a variety thereof regarding the layered body by plating to be produced thereby. And then thereafter there is performed a process of treating with heat for such the layered body by plating, and hence there is produced the following individual samples of the metallic material as the sample numbers of 1 to 3 that individually have the configurations as shown in FIG. 4 and FIG. 6 through FIG. 17 respectively. Here FIG. 4 corresponds to the sample number as 1 of the metallic material, meanwhile, all of FIG. 6 through FIG. 10 correspond to the sample number as 2 of the metallic material, meanwhile, all of FIG. 11 through FIG. 17 correspond to the sample number as 3 of the metallic material.

[0080] As more specifically, there is performed the production of the individual layered bodies by plating with designing each of the volume ratios of between the volume of the S-layer and that of the C-layer as the (S/C) to be as shown in the following Table 2. And then thereafter there is performed a treatment for such the individual layered bodies by plating by making use of a method of treating with heat therefor (a method of batch processing or a method of reflow processing) that is shown in Table 2 as well. And hence there is produced each of the samples of the metallic material as the sample numbers of 1 to 3. Here regarding CONDITION OF HEAT TREATMENT in Table 2, there is indicated a temperature at an inside of a furnace for a treatment with heat in a case of batch processing therefor, meanwhile, there is indicated a temperature at an inside of a reflow furnace for a treatment with heat in a case of reflow processing therefor on the contrary thereto. Moreover, there is designed to be fixed such the temperature at the inside of the reflow furnace to be at approximately 740 °C in accordance with Table 2.

[0081] Further, regarding each of such the metallic materials to be obtained thereby, first of all there is performed for each of the samples with the oblique section of thirty degrees by making use of the focused ion beam (FIB) with setting the same to be inclined as sixty degrees, and each of such the samples is assumed to be as the sample for the Auger analysis and measurement (AES). Still further, there is performed such the analysis of the AES with each of such the samples to be inclined for having the oblique section of thirty degrees to become horizontal. And hence there becomes to be obtained each of the individual electron images of the AES, and then by making thereof there is measured a thickness of each of the layers thereon. Furthermore, there is shown a configuration of each of such the samples in the following Table 2.

SAMPLE NUMBER	VOLUME RATIO OF LAYERED BODY BY PLATING: S-LAYER / C-LAYER	CONDITION OF HEAT TREATMENT	CONFIGURATION OF PLATING MATERIAL (μm)		
			UNDERLAYER	INTERMEDIATE LAYER	OUTERMOST LAYER
1	1.85	160□×120hr	Ni 0.4	Cu 0.02	Cu-Sn 2.0
2	1.00	740□×7sec	Ni 0.4	Cu 0.05	Cu-Sn 0.35
3	0.63	740□×7sec	Ni 0.4	Cu 0.36	Cu-Sn 0.45

[0082] Next, there is performed a test for slight sliding regarding each of such the obtained samples as the sample numbers of 1 to 3 till the number of times for going and coming back of the slight sliding reaching to 1000 times, that will be described below. And then there is performed a measurement as continuously regarding a variation of a value

of the contact resistance of therebetween. Moreover, there is performed such the test for slight sliding thereof as the following description.

[0083] That is to say, there is prepared the metallic materials as one pair of 41 and 42 as shown in FIG. 18, that there is provided a projected part of hemispheric shape 41a which has a radius of curvature as 1.8 mm with being performed a reflow plating of Sn for an outside surface of the projected convex part to have a thickness of approximately 1 μm on the metallic material 41, and that the metallic material 42 comprises an alloy layer of Cu-Sn 42a. Moreover, there is performed a process of cleaning for removing any grease from both of such the materials, and then thereafter there is contacted to therebetween with a contact pressure of 3 N. Further, there is performed a sliding for going and coming back the both of such the materials with a distance for sliding as 30 μm under an environment at a temperature of 20 $^{\circ}\text{C}$ and with a humidity of 65 % approximately. Further, there is flowed a constant electrical current as 5 mA with applying an open circuit voltage as 20 mV to between the metallic material 41 and the 42. Still further, there is measured a fall of voltage at the period of sliding therebetween by making use of a four terminal method, and then there is evaluated the variation of the electrical resistance thereof for every one second. Here there is shown a value of the contact resistance before performing the test for slight sliding (an initial value) and a maximum value of the contact resistance at the period of performing the test for slight sliding (a maximum value) in the following Table 3. Still further, there is performed such the movement of going and coming back with a frequency of approximately 3.3 Hz. Still further, there is measured a coefficient of dynamic friction for each thereof by making use of a friction tester of the Bowden type under the following conditions of the load as 2.94 N, the distance of sliding as 10 mm, the velocity of sliding as 100 mm/min and the number of times for sliding as one time. Still further, there is made use of a partner material therefor on which there is performed a work for forming a projected part to have a curvature of 0.5 mm R after performing a reflow plating of Sn with a thickness of approximately 1 μm onto a bar material of brass which has a plate thickness of 0.25 mm approximately. Furthermore, there is shown both in Table 3 regarding each of the results from such the individual measurements for each of the coefficient of friction.

SAMPLE NUMBER	CONTACT RESISTANCE		COEFFICIENT OF FRICTION
	INITIAL VALUE	MAXIMUM VALUE OF SLIDING	
1	GOOD	GOOD	0.18
2	GOOD	GOOD	0.19
3	GOOD	GOOD	0.24
(INITIAL VALUE: $\text{GOOD} \leq 3 \text{ m}\Omega$, <u>NO GOOD</u> $> 3 \text{ m}\Omega$)			
(MAXIMUM VALUE OF SLIDING: $\text{GOOD} \leq 10 \text{ m}\Omega$, <u>NO GOOD</u> $> 10 \text{ m}\Omega$)			

(Example 2)

[0084] Here there is performed a production of a layered body by performing the process of the electroplating of Ni and then Cu and then Sn as the layered formation in such order onto each of the substrates of the alloy of copper as similar to that in accordance with the above Example 1, that comprises each of the plating layers which individually have the thicknesses as shown in the following Table 4. Moreover, there is performed a production of a connector that is comprised of the individual male terminals in accordance with the following Comparative example 1 and the following Present invention example 1 to 4, and the individual female terminals that individually are connectable with such the corresponding male terminals respectively, with making use of each of the materials which is performed the process of the reflow treatment under the conditions of treating with heat therefor as shown in the above Table 1 (the temperature thereof and the amount of time therefor), and that are shown in FIG. 1 and in FIG. 2. Further, there becomes for the surface of the female terminal in accordance with Present invention example 1 and for the surface of the male terminal in accordance with Present invention example 3 to be formed as the alloy of Cu-Sn individually for all over the individual surfaces thereof as shown in FIG. 6 through FIG. 10 by making use of the above mentioned process of reflow treatment therefor. Furthermore, there becomes for the surface of the female terminal in accordance with Present invention example 2 and for the surface of the male terminal in accordance with Present invention example 4 to be formed with the Sn being diffused partially into each of the alloy layers of Cu-Sn individually as shown in FIG. 11 through FIG. 15 by making use of such the process therefor on the contrary thereto.

	COMPARATIVE EXAMPLE 1		PRESENT INVENTION EXAMPLE 1	
	MALE	FEMALE	MALE	FEMALE
	Cu ALLOY	Cu ALLOY	Cu ALLOY	Cu ALLOY
PURE Sn LAYER	0.8	0.8	0.8	0.3
Cu LAYER	0.3	0.3	0.3	0.3
Ni LAYER	0.5	0.5	0.5	0.5
BASE SUBSTANCE	COPPER ALLOY	COPPER ALLOY	COPPER ALLOY	COPPER ALLOY
HEAT TREATMENT TEMPERATURE (°C) TIMES (x) RETENTION TIME (S)	740□ x 7sec	740□ x 7sec	740□ x 7sec	740□ x 7sec

	PRESENT INVENTION EXAMPLE 2		PRESENT INVENTION EXAMPLE 3	
	MALE	FEMALE	MALE	FEMALE
	Cu ALLOY	Cu ALLOY	Cu ALLOY	Cu ALLOY
PURE Sn LAYER	0.8	0.5	0.3	0.8
Cu LAYER	0.3	0.6	0.3	0.3
Ni LAYER	0.5	0.5	0.5	0.5
BASE SUBSTANCE	COPPER ALLOY	COPPER ALLOY	COPPER ALLOY	COPPER ALLOY
HEAT TREATMENT TEMPERATURE (°C) TIMES (x) RETENTION TIME (S)	740□ x 7sec	740□ x 7sec	740□ x 7sec	740□ x 7sec

	PRESENT INVENTION EXAMPLE 4	
	MALE	FEMALE
	Cu ALLOY	Cu ALLOY
PURE Sn LAYER	0.5	0.8
Cu LAYER	0.6	0.3
Ni LAYER	0.5	0.5
BASE SUBSTANCE	COPPER ALLOY	COPPER ALLOY
HEAT TREATMENT TEMPERATURE (°C) TIMES (x) RETENTION TIME (S)	740□ x 7sec	740□ x 7sec

[0085] Next, there is performed a test of force for insertion by making use of the method in accordance with the explanatory drawing as schematically shown in the drawing from a side view of FIG. 19 with making use of the individual male terminals and the individual female terminals in accordance with such the above mentioned Present invention examples and Comparative example. That is to say, there is fixed a female terminal 51 by making use of a treatment device 53, and then there is inserted a male terminal 52 into a treatment device for pushing 54 with a velocity thereof as 50 mm/min in a direction to an axis thereof (in the direction to the regular insertion of such the terminal at the time of the engagement for the connector). Moreover, there is performed a monitoring regarding a curved line of between a displacement thereof and a load thereto at such the period thereof by making use of a monitor 57 which is connected to a load cell 55 and to a displacement gauge 56. And then there is recorded a peak value of loading for such the terminal at a period till reaching to the regular position of the engagement thereof to be assumed as a force for inserting the single terminal. Further, there is shown such the monitor 57 with making use of the drawing from a diagrammatic perspective view in order to understand as easier. Still further, there is performed such the measurements with the

number of times as five times for each of the sample terminals, and then there is performed an calculation for evaluating an average value thereof. Furthermore, there is shown each of such the results thereof in the following Table 5.

	N
COMPARATIVE EXAMPLE 1	2.58
PRESENT INVENTION EXAMPLE 1	2.48
PRESENT INVENTION EXAMPLE 2	2.32
PRESENT INVENTION EXAMPLE 3	2.26
PRESENT INVENTION EXAMPLE 4	2.22

[0086] Here regarding each of the connectors in accordance with Present invention example 1 through 4 as shown in Table 5, it becomes able to reduce the force for inserting thereinto as not less than 0.1 N as comparing to the connector in accordance with Comparative example 1, and then thereby it becomes able to obtain the property of insertion thereinto and of extraction therefrom as further excellently.

[0087] Next, there is performed an insertion of a terminal which is finished jointing with an electric wire by pressing thereon into a housing of a connector which is provided at each of the female terminal 51 and the male terminal 52. And then thereafter such the sample as a state to be engaged with each other is put into a constant temperature bath, and then there is maintained such the sample at a temperature of 120 ± 3 °C with an amount of time for 120 hours. And then thereafter such the sample is taken out from the constant temperature bath, and then the same is remained till the temperature thereof to be as same as a room temperature. Moreover, there is set thereafter such the sample to be as shown in a circuit diagram of FIG. 20, and then there is charged with electricity with making use of an electric power supply 61 under the condition of 20 ± 5 mV at a period of opening the circuit and of 10 ± 0.5 mA at a period of closing the circuit. And then there is performed a measurement of a voltage with making use of a voltmeter 62 at a position as 100 mm from either one of the terminals of the male or the female respectively. Further, there is performed a calculation to evaluate a value of resistance by making use of the individual values of voltage and the electrical current to be charged with electricity that are measured thereby. Still further, there is performed a calculation to evaluate a value of resistance regarding the terminal part after maintaining at a temperature as higher by subtracting the value of resistance as 6.54 mΩ for the electric wire with the length thereof as 200 mm. Still further, there is shown each of the results therefrom in the following Table 6. Still further, there is performed a calculation to evaluate a value of resistance as similar thereto regarding the connector at a state before being put into the constant temperature bath, and then there is performed a calculation to evaluate an initial value of resistance therefor. Still further, there is performed a calculation to evaluate an increased value thereof against the above mentioned value of resistance after being maintained at the higher temperature as well. And hence there is shown each of such the values together in Table 6 as well. Furthermore, a unit for each of such the values of resistance in Table 6 is defined here to be as mΩ respectively.

	INITIAL STAGE	AFTER MAINTAINING AT HIGH TEMPERATURE	INCREASED VALUE
COMPARATIVE EXAMPLE 1	2.12	2.72	0.60
PRESENT INVENTION EXAMPLE 1	2.15	2.48	0.33
PRESENT INVENTION EXAMPLE 2	2.22	2.76	0.54
PRESENT INVENTION EXAMPLE 3	2.29	2.58	0.29
PRESENT INVENTION EXAMPLE 4	2.19	2.52	0.33

[0088] Here regarding the connectors in accordance with Present invention examples 1 through 4, it is found out as shown in Table 6 that each of the increased values of the resistance is smaller than that in accordance with Comparative example 1 in spite of the thickness of each of the metal layers therein as thinner in comparison with the connector in accordance with Comparative example 1, and hence that it becomes able to obtain the electrical connectability therebetween as further excellently and further stably for such the connector.

Industrial Applicability

[0089] Here it becomes able to apply such the connector in accordance with the present invention as preferred to a connector to be made use for such as a motor vehicle, for an electrical device and for an electronic device, for an electrical component and for an electronic component, or the like.

[0090] Moreover, it becomes able to apply such the metallic material for the connector in accordance with the present invention as preferred to a material to be made use for such as a contact member part of a male terminal or of a female terminal, for the connectors as a variety types thereof that are mentioned above, for a contact shoe, or the like.

[0091] Thus, there is described as above regarding the present invention in reference to the embodiment therefor, however, the present invention will not be limited to every detail of the description as far as a particular designation therefor, and it should be interpreted widely without departing from the spirit and scope of the present invention as disclosed in the attached claims.

[0092] Furthermore, the present invention claims the priority based on Japanese Patent Application No. 2007-102099, that is patent applied in Japan on the ninth day of April 2007.

Claims

1. A metallic material for a connector, comprising:

an electrically conductive substrate (1);
 an underlayer (2) composed of Ni, a Ni alloy, Fe, an Fe alloy, Co, or a Co alloy;
 an intermediate layer (3) composed of Cu or a Cu alloy; and
 an outermost layer (4) composed of a Cu-Sn alloy layer, in this order from the substrate,
characterized in that the alloy layer of Cu-Sn has a structure that a concentration of Cu is decreased gradually toward the surface of the Cu-Sn alloy layer; and wherein Sn or an alloy of Sn is dispersed in the alloy layer of Cu-Sn.

2. The metallic material for the connector according to claim 1, wherein at least a part of the Sn or Sn alloy is exposed on a surface of the Cu-Sn alloy layer, and the Sn or Sn alloy is dispersed as an island shape or as a spot shape in a cross-sectional view.

3. The metallic material for the connector according to claim 1 or 2, wherein the Cu-Sn alloy layer is formed by thermal diffusion as mutually between a plating layer of Cu or a Cu alloy and a plating layer of Sn or a Sn alloy, with said plating layers being adjacent to each other.

4. A connector, comprising:

a male connector which comprises a male terminal; and
 a female connector which comprises a female terminal,
 wherein the male connector and the female connector are arranged to be connectable with each other, and
 wherein an outermost layer of at least one of the male terminal and the female terminal is made of the metallic material of any one of claims 1 to 3.

5. The connector of claim 4,
 wherein only an outermost surface of a contact portion of at least one of the male terminal and the female terminal is formed with the metallic material.

6. The connector of claim 4,
 wherein at least a contact portion of one of the male terminal or the female terminal is formed with the metallic material, and
 wherein at least a contact portion of the other of the male terminal or the female terminal is formed with a metallic material whose outermost surface layer is a Sn or Sn alloy layer.

7. The connector according to claim 6,
 wherein at least a contact portion of the male terminal is formed with the metallic material having the Cu-Sn alloy layer as the outermost layer, and at least a contact portion of the female terminal is formed with the metallic material having the Sn or Sn alloy layer as the outermost layer.

8. A method for producing a metallic material for a connector according to claim 1, comprising the steps of:

forming a plating layer of Cu or a Cu alloy and forming a plating layer of Sn or a Sn alloy, with said plating layers being adjacent to each other;

performing a heat treatment, to cause thermal diffusion between the plating layer of Cu or the Cu alloy and the plating layer of Sn or the Sn alloy, thereby forming the Cu-Sn alloy layer.

9. The method according to claim 8, wherein the heat treatment is a process comprising: passing the metallic material with the plating layer of Cu or the Cu alloy and the plating layer of Sn or the Sn alloy through a reflow furnace with a temperature in the furnace of 300 °C to 800 °C for a time period of 3 seconds to 20 seconds.

10. The method for producing the metallic material for the connector according to claim 8 or 9, comprising:

after the heat treatment, performing cooling by passing through a liquid with a temperature of 20°C to 80°C for a time period of 1 second to 100 seconds.

11. The method according to claim 8 or 9, comprising:

after the heat treatment, performing cooling by passing through a gas with a temperature of 20°C to 60°C for a time period of 1 second to 300 seconds; and

performing cooling by passing through a liquid with a temperature of 20°C to 80°C for a time period of 1 second to 100 seconds.

Patentansprüche

1. Metallisches Material für einen Verbinder, aufweisend:

ein elektrisch leitendes Substrat (1);

eine untere Schicht (2), welche aus Ni, einer Ni-Legierung, Fe, einer Fe-Legierung, Co oder einer Co-Legierung gebildet ist;

eine Zwischenschicht (3), welche aus Cu oder einer Cu-Legierung gebildet ist; und

eine äußerste Schicht (4), welche aus einer Cu-Sn-Legierungsschicht gebildet ist, in dieser Reihenfolge von dem Substrat aus,

dadurch gekennzeichnet, dass die Legierungsschicht aus Cu-Sn eine Struktur derart aufweist, dass eine Konzentration von Cu graduell in Richtung der Oberfläche der Cu-Sn-Legierungsschicht verringert ist; und wobei Sn oder eine Legierung aus Sn in der Legierungsschicht aus Cu-Sn verteilt ist.

2. Metallisches Material für den Verbinder nach Anspruch 1, wobei zumindest ein Teil von dem Sn oder der Sn-Legierung an einer Oberfläche von der Cu-Sn-Legierungsschicht freigelegt ist, und das Sn oder die Sn-Legierung in einer Querschnittsansicht inselförmig oder punktförmig verteilt ist.

3. Metallisches Material für den Verbinder nach Anspruch 1 oder 2, wobei die Cu-Sn-Legierungsschicht mittels wechselseitiger thermaler Diffusion zwischen einer Beschichtungsschicht aus Cu oder aus einer Cu-Legierung und einer Beschichtungsschicht aus Sn oder einer Sn-Legierung gebildet ist, wobei die Beschichtungsschichten benachbart zueinander sind.

4. Verbinder, aufweisend:

einen Stecker mit einem Steckanschluss; und

eine Buchse mit einem Buchsenanschluss,

wobei der Stecker und die Buchse eingerichtet sind, um miteinander verbindbar zu sein, und

wobei eine äußerste Schicht von dem Steckanschluss und/oder dem Buchsenanschluss aus dem metallischen Material nach einem der Ansprüche 1 bis 3 hergestellt ist.

5. Verbinder nach Anspruch 4, wobei nur eine äußerste Oberfläche von einem Kontaktabschnitt von dem Steckanschluss und/oder dem Buchsenanschluss mit dem metallischen Material gebildet ist.

6. Verbinder nach Anspruch 4, wobei zumindest ein Kontaktabschnitt von dem Steckanschluss und/oder dem Buchsenanschluss mit dem metallischen Material gebildet ist, und wobei zumindest ein Kontaktabschnitt von dem Anderen von dem Steckanschluss oder dem Buchsenanschluss mit einem metallischen Material gebildet ist, dessen äußerste Oberflächenschicht eine Sn-Schicht oder Sn-Legierungsschicht ist.

7. Verbinder nach Anspruch 6, wobei zumindest ein Kontaktabschnitt des Steckanschlusses aus dem metallischen Material gebildet ist, welches die Cu-Sn-Legierungsschicht als äußerste Schicht aufweist, und zumindest ein Kontaktabschnitt des Buchsenanschlusses aus dem metallischen Material gebildet ist, welches die Sn-Schicht oder die Sn-Legierungsschicht als äußerste Schicht aufweist.

8. Verfahren zum Herstellen eines metallischen Materials für einen Verbinder nach Anspruch 1, mit den Schritten:

Ausbilden einer Beschichtungsschicht aus Cu oder einer Cu-Legierung und Ausbilden einer Beschichtungsschicht aus Sn oder einer Sn-Legierung, wobei die Beschichtungsschichten benachbart zueinander sind; Durchführen einer Wärmebehandlung, um eine thermische Diffusion zwischen der Beschichtungsschicht aus Cu oder der Cu-Legierung und der Beschichtungsschicht aus Sn oder der Sn-Legierung zu verursachen, um dadurch die Cu-Sn-Legierungsschicht zu bilden.

9. Verfahren nach Anspruch 8, wobei die Wärmebehandlung ein Prozess ist, der umfasst: Durchfahren des metallischen Materials mit der Beschichtungsschicht aus Cu oder der Cu-Legierung und der Beschichtungsschicht aus Sn oder der Sn-Legierung durch einen Rückfluss-Ofen mit einer Temperatur in dem Ofen von 300°C bis 800°C für einen Zeitraum von 3 Sekunden bis 20 Sekunden.

10. Verfahren zum Herstellen des metallischen Materials für den Verbinder nach Anspruch 8 oder 9, aufweisend:

nach der Wärmebehandlung, Ausführen einer Kühlung mittels Durchführen durch eine Flüssigkeit mit einer Temperatur von 20°C bis 80°C für einen Zeitraum von 1 Sekunde bis 100 Sekunden.

11. Verfahren nach Anspruch 8 oder 9, aufweisend:

nach der Wärmebehandlung, Durchführen einer Kühlung mittels Durchführen durch ein Gas mit einer Temperatur von 20°C bis 60°C für einen Zeitraum von 1 Sekunde bis 300 Sekunden; und Durchführen einer Kühlung mittels Durchführen durch eine Flüssigkeit mit einer Temperatur von 20°C bis 80°C für einen Zeitraum von 1 Sekunde bis 100 Sekunden.

Revendications

1. Matériau métallique pour un connecteur, comprenant :

un substrat conducteur d'électricité (1) ;
une sous-couche (2) constituée de Ni, d'un alliage de Ni, de Fe, d'un alliage de Fe, de Co, ou d'un alliage de Co ;
une couche intermédiaire (3) composée de Cu ou d'un alliage de Cu ; et une couche la plus externe (4) composée d'une couche d'alliage de Cu-Sn, dans cet ordre à partir du substrat,
caractérisé en ce que la couche d'alliage de Cu-Sn a une structure dans laquelle une concentration de Cu est réduite progressivement vers la surface de la couche d'alliage de Cu-Sn ; et dans lequel du Sn ou un alliage de Sn est dispersé dans la couche d'alliage de Cu-Sn.

2. Matériau métallique pour le connecteur selon la revendication 1, dans lequel au moins une partie du Sn ou de l'alliage de Sn est exposée sur une surface de la couche d'alliage de Cu-Sn, et le Sn ou l'alliage de Sn est dispersé sous une forme d'îlot ou sous une forme de point dans une vue en coupe transversale.

3. Matériau métallique pour le connecteur selon la revendication 1 ou 2, dans lequel la couche d'alliage de Cu-Sn est formée par diffusion thermique mutuellement entre une couche de placage de Cu ou d'un alliage de Cu et une couche de placage de Sn ou d'un alliage de Sn, lesdites couches de placage étant adjacentes l'une à l'autre.

4. Connecteur, comprenant :

un connecteur mâle qui comprend une borne mâle ; et
 un connecteur femelle qui comprend une borne femelle,
 dans lequel le connecteur mâle et le connecteur femelle sont agencés de manière à pouvoir être connectés
 l'un avec l'autre, et
 dans lequel une couche la plus externe d'au moins l'une de la borne mâle et de la borne femelle est constituée
 du matériau métallique selon l'une quelconque des revendications 1 à 3.

5. Connecteur selon la revendication 4,
 dans lequel seule une surface la plus externe d'une partie de contact d'au moins l'une de la borne mâle et de la
 borne femelle est formée avec le matériau métallique.

6. Connecteur selon la revendication 4,
 dans lequel au moins une partie de contact de l'une de la borne mâle ou de la borne femelle est formée avec le
 matériau métallique, et
 dans lequel au moins une partie de contact de l'autre de la borne mâle ou de la borne femelle est formée avec un
 matériau métallique dont la couche de surface la plus externe est une couche de Sn ou d'un alliage de Sn.

7. Connecteur selon la revendication 6,
 dans lequel au moins une partie de contact de la borne mâle est formée avec le matériau métallique ayant la couche
 d'alliage de Cu-Sn en tant que la couche la plus externe, et au moins une partie de contact de la borne femelle est
 formée avec le matériau métallique ayant la couche de Sn ou d'alliage de Sn en tant que la couche la plus externe.

8. Procédé de production d'un matériau métallique pour un connecteur selon la revendication 1, comprenant les étapes
 consistant à :

former une couche de placage de Cu ou d'un alliage de Cu et former une couche de placage de Sn ou d'un
 alliage de Sn, lesdites couches de placage étant adjacentes l'une à l'autre ;
 effectuer un traitement thermique pour provoquer la diffusion thermique entre la couche de placage de Cu ou
 de l'alliage de Cu et la couche de placage de Sn ou de l'alliage de Sn, pour ainsi former la couche d'alliage de
 Cu-Sn.

9. Procédé selon la revendication 8, dans lequel le traitement thermique est un procédé comprenant :

faire passer le matériau métallique avec la couche de placage de Cu ou de l'alliage de Cu et la couche de
 placage de Sn ou de l'alliage Sn dans un four de refusion avec une température dans le four de 300 °C à 800
 °C pendant une période de temps comprise entre 3 secondes et 20 secondes.

10. Procédé de production du matériau métallique pour le connecteur selon la revendication 8 ou 9, comprenant :

après le traitement thermique, effectuer un refroidissement en passant dans un liquide à une température de
 20 °C à 80 °C pendant une période de temps comprise entre 1 seconde et 100 secondes.

11. Procédé selon la revendication 8 ou 9, comprenant :

après le traitement thermique, effectuer un refroidissement en passant dans un gaz ayant une température de
 20 °C à 60 °C pendant une période de temps comprise entre 1 seconde et 300 secondes ; et
 effectuer un refroidissement en passant dans un liquide à une température de 20 °C à 80 °C pendant une
 période de temps comprise entre 1 seconde et 100 secondes.

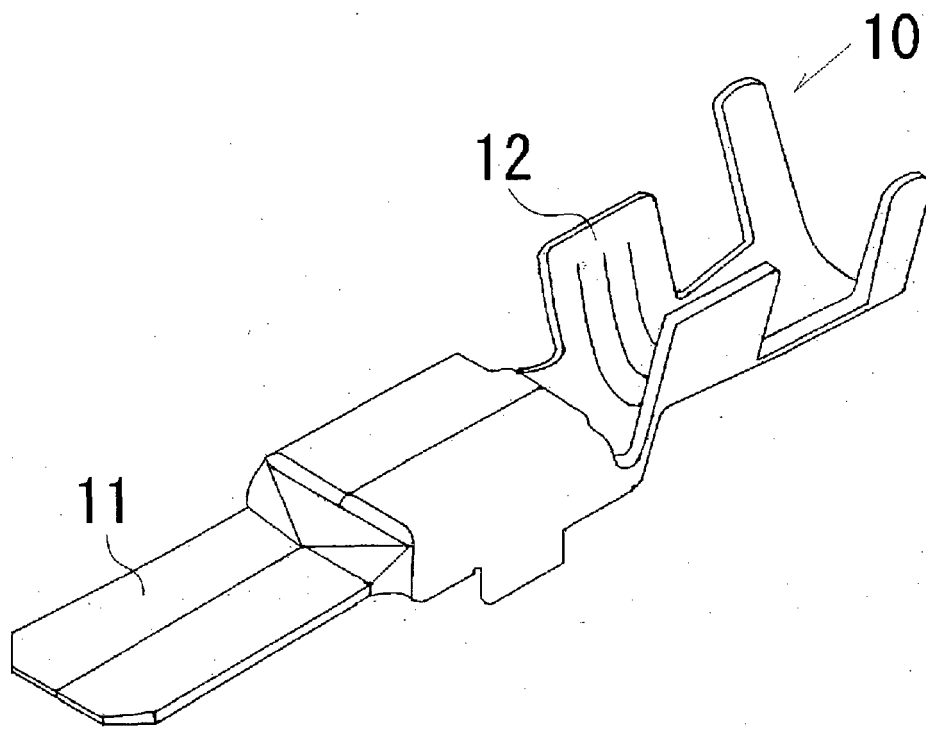


Figure 1

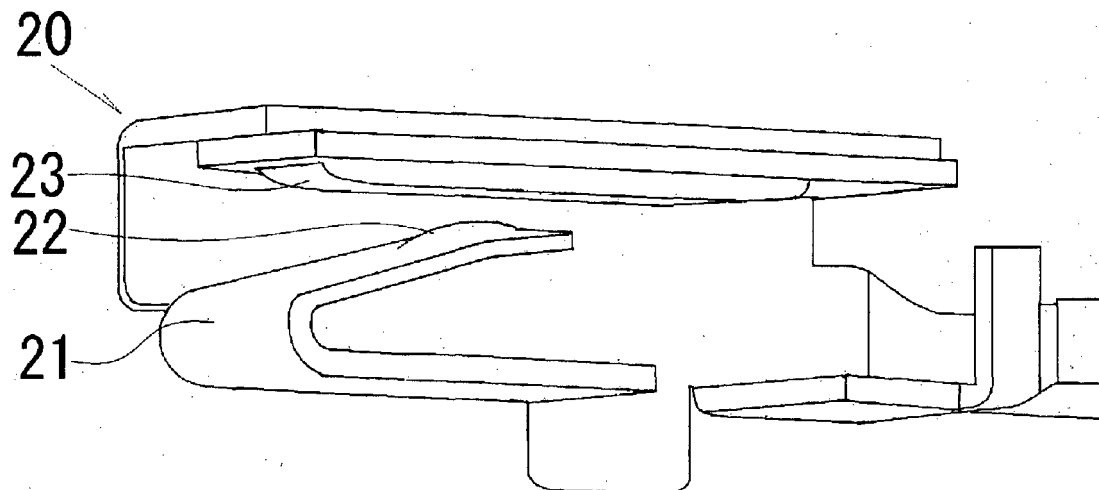


Figure 2

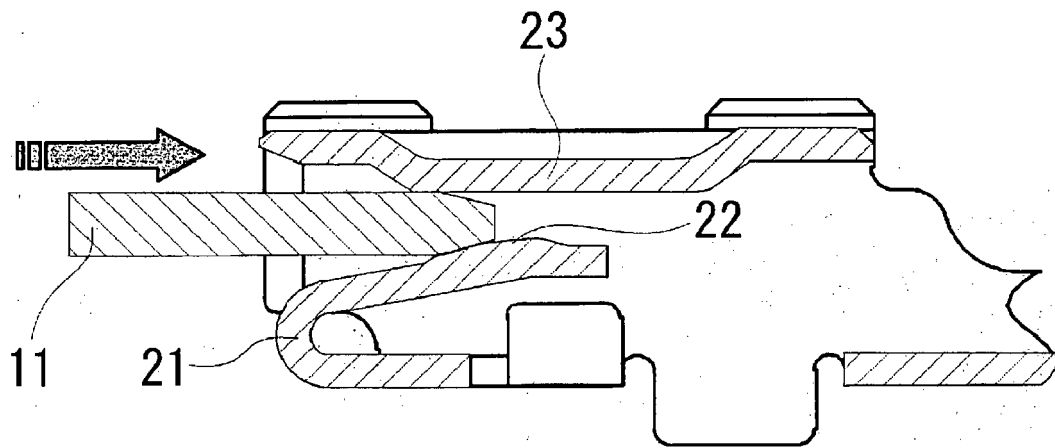


Figure 3

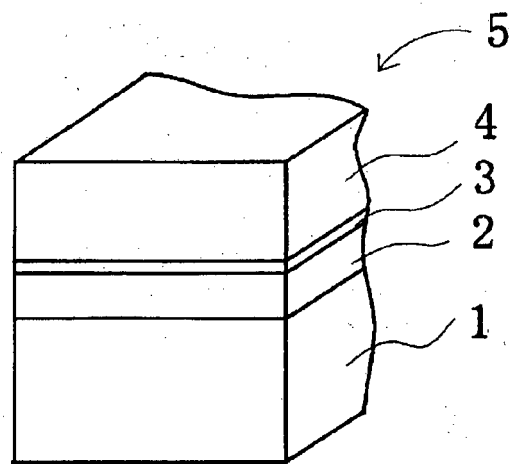


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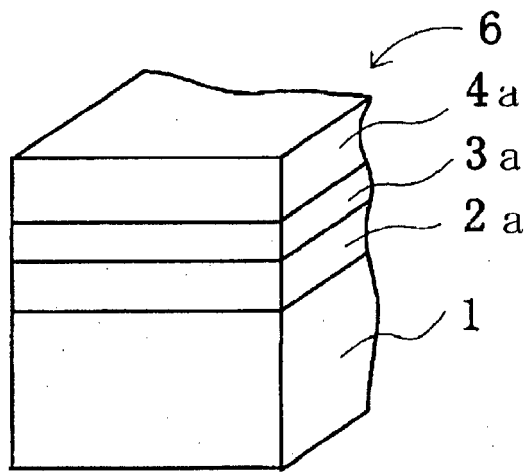


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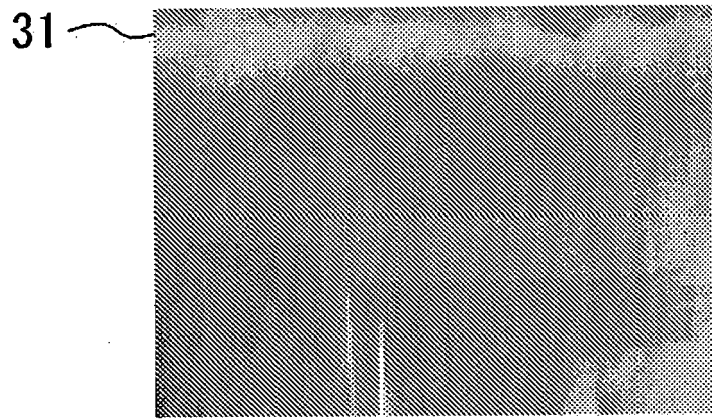


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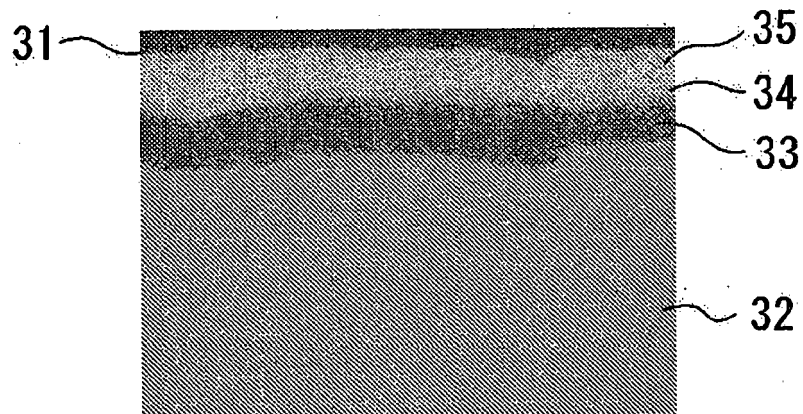


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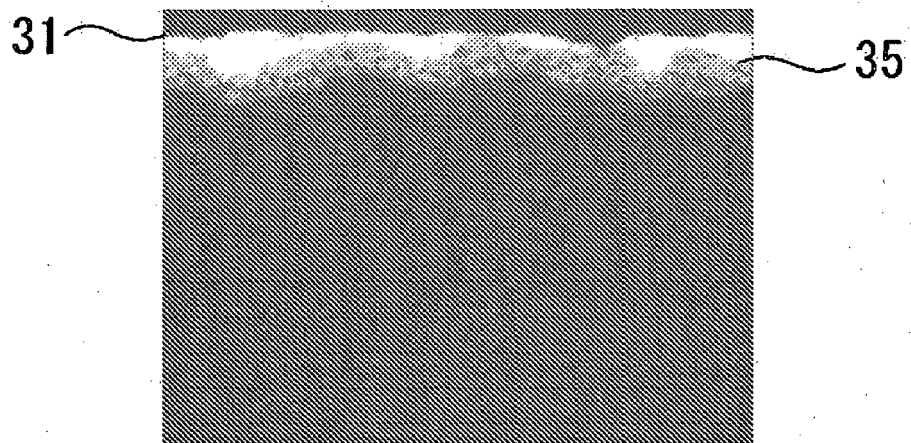


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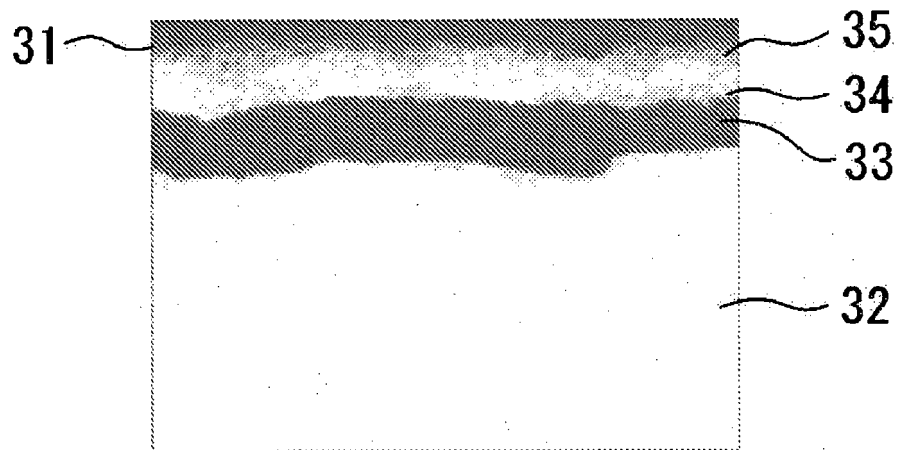


Figure 9

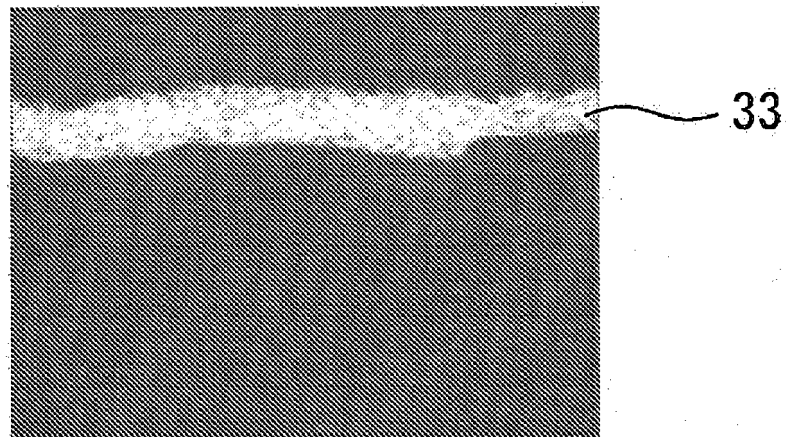


Figure 10

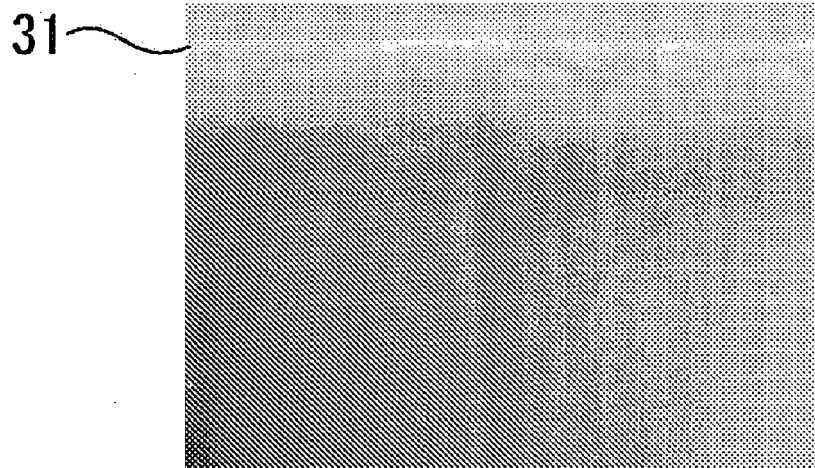


Figure 11

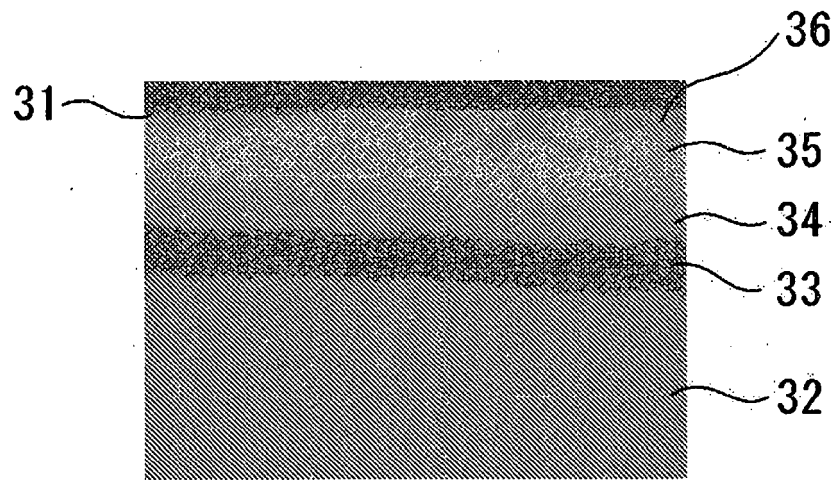


Figure 12

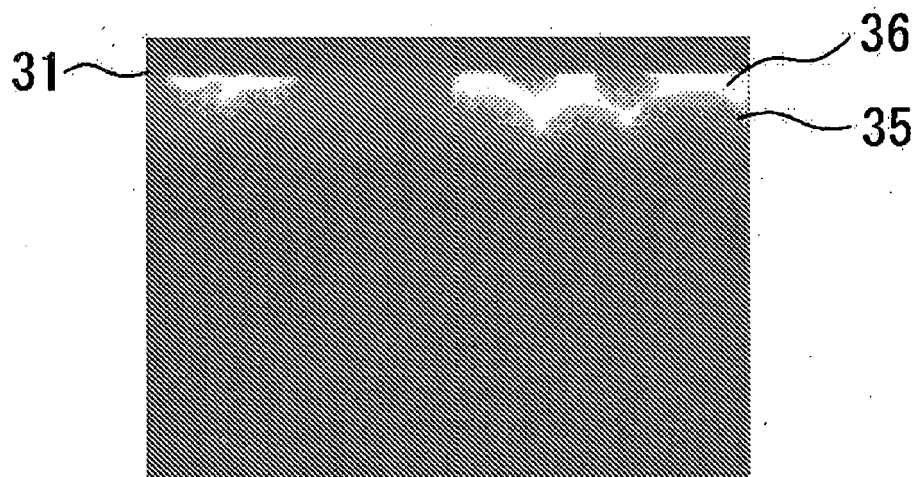


Figure 13

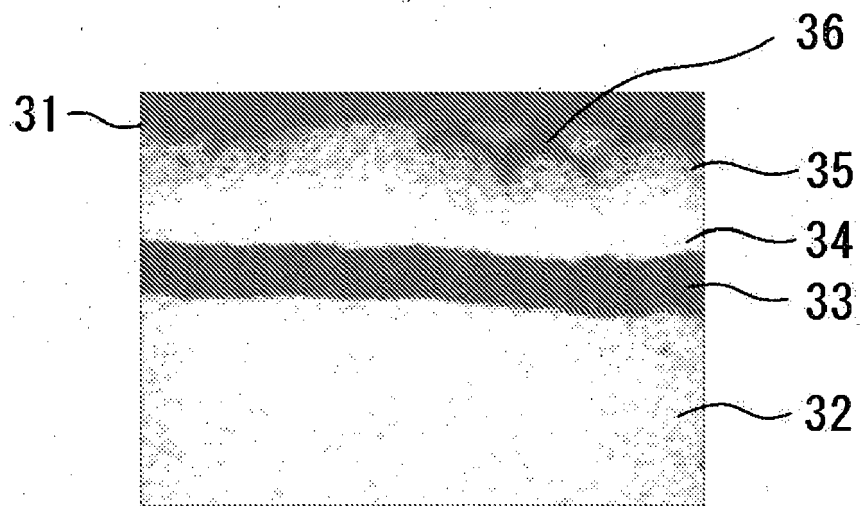


Figure 14

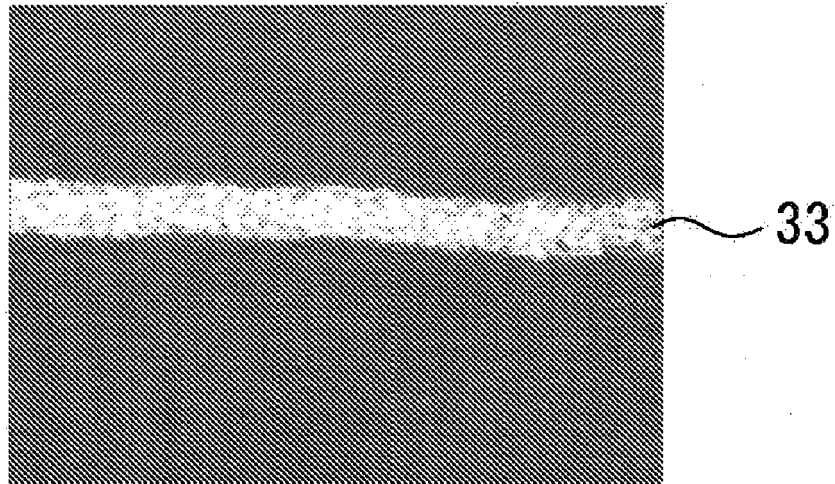


Figure 15

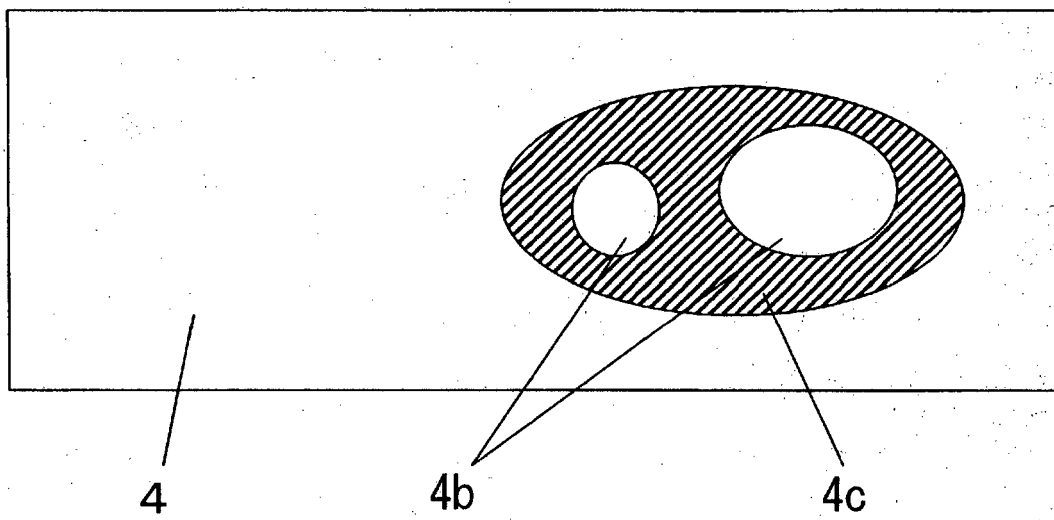


Figure 16

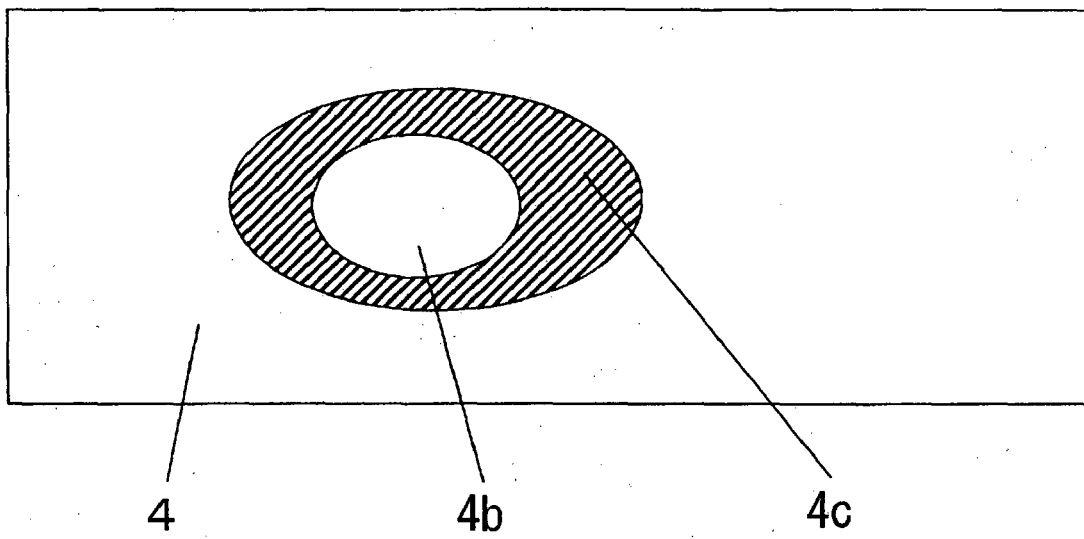


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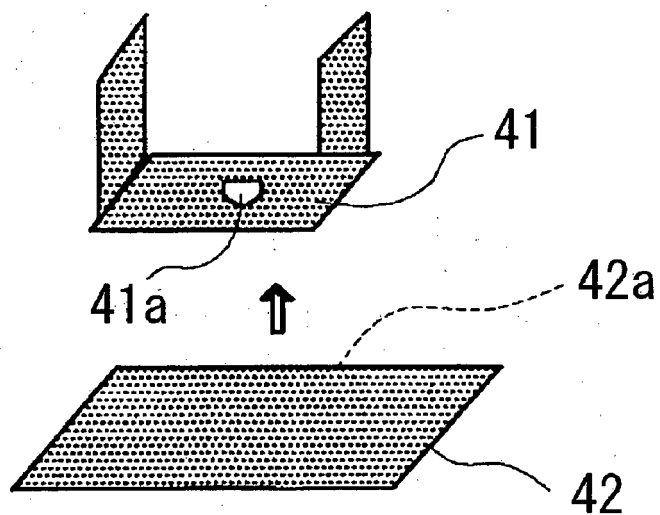


Figure 18

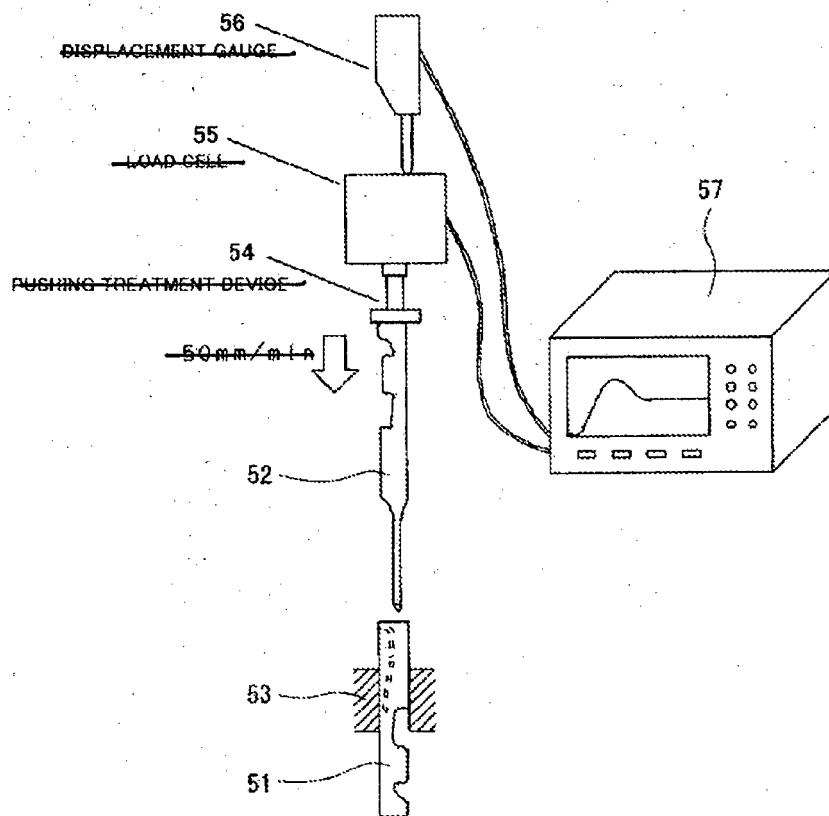


Fig. 19

Figure 19

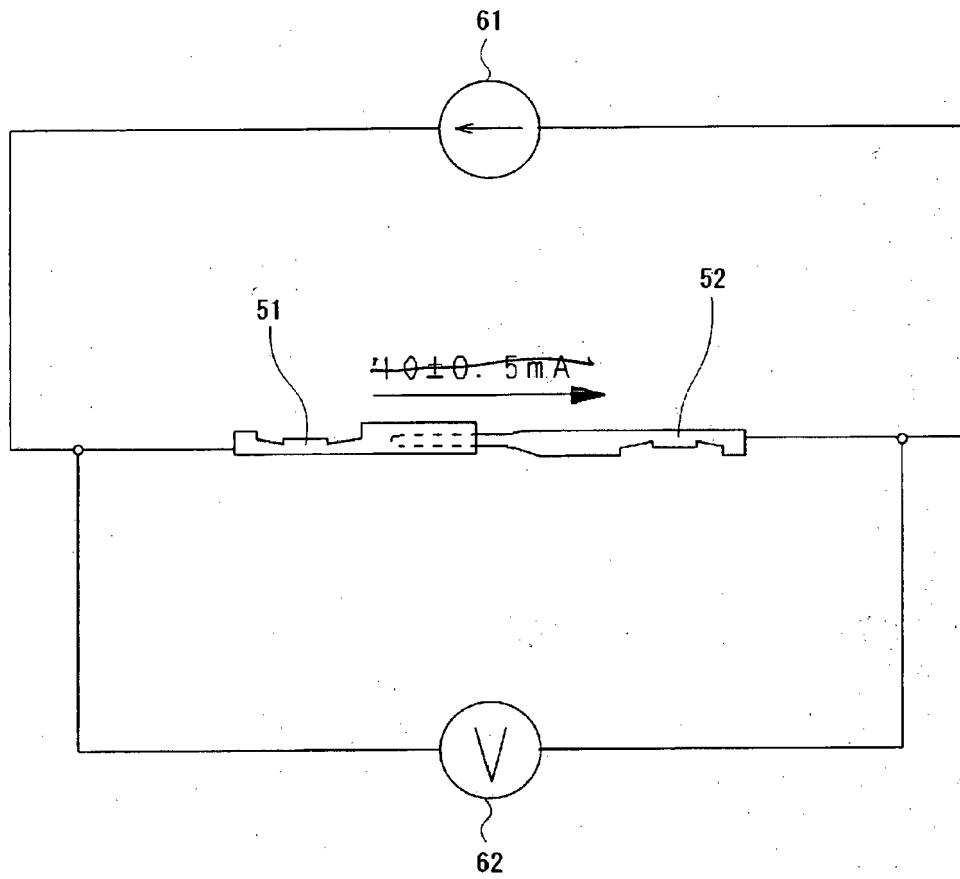


Figure 20

REFERENCES CITED IN THE DESCRIPTION

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Patent documents cited in the description

- JP 2004179055 A [0009]
- JP 2000021545 A [0009]
- JP 2003082499 A [0009]
- JP 2004339555 A [0009]
- JP 2000212720 A [0009]
- JP 2000226645 A [0009]
- JP 2004068026 A [0009]
- JP 2003213486 A [0009]
- US 2003091855 A [0010]
- JP 2007102099 A [0092]